PY32F071 Datasheet

32-bit ARM® Cortex®-M0+ Microcontroller

Puya Semiconductor (Shanghai) Co., Ltd

PY32F071 Series

ARM® 32-bit Cortex®-M0+ Microcontroller

Datasheet

Features

- Core
  - ARM® 32-bit Cortex®-M0+ CPU
  - Up to 72 MHz operating frequency
- Memories
  - Maximum 128K/ 96K/ 64K/ 32K bytes Flash memory
  - Maximum 16K/ 12K/ 8K/ 4K bytes SRAM
- Clock management
  - Internal 4/8/16/22.12/24 MHz high speed clock (HSI)
  - Internal 32.768 kHz low speed clock (LSI)
  - External 4 to 32 MHz high speed crystal oscillator (HSE)
  - External 32.768 kHz low-speed crystal oscillator (LSE)
  - PLL (supports 2/3 multiplication of HSI or HSE)
- Power management and reset
  - Operating voltage: 1.7 to 5.5 V
  - Low power modes : Sleep and Stop
  - Power-on/power- down reset (POR/PDR)
  - Brown-out reset (BOR)
  - Programmable voltage detection (PVD)
- General-purpose input and output (I/O)
  - Up to 58 I/Os, all available as external interrupts
  - Drive current 8 mA
- 7-channel DMA controller
- Two 12-bit ADC
  - Up to 16 external input channels
  - Input voltage conversion range: 0 to V_{CCA}
- Two 12-bit DAC, supports 2 channels
- 3 analog comparators
- 3-channel operational amplifier
- Support 8 * 36 / 4 * 40 LCD
- 13 timers
  - One 16-bit advanced-control timer (TIM1)
  - One 32-bit general-purpose timer (TIM2)
  - Five 16-bit general-purpose timers (TIM3/14/15/16/17)
  - Two basic timers (TIM6/TIM7)
  - A low power timer (LPTIM)
  - A independent watchdog timer (IWDT)
  - A window watchdog timer (WWDT)
  - A SysTick timer
- RTC
- Communication interfaces
  - Two serial peripheral interfaces (SPI) with I^2S function
  - Four universal synchronous/asynchronous Transceivers (USARTs) , support automatic baud rate detection, two of USARTs support ISO7816, LIN and IrDA
  - Two I^2C interfaces supporting standard mode (100 kHz), Fast mode (400 kHz), 7-bit/10-bit addressing mode and SMBus
  - USB 2.0 full-speed interface
- Hardware CRC-32 module
- Hardware 32-bit divider
- Unique UID
- Serial wire debug (SWD)
- Operating temperature: -40 ~ 85 ℃，-40 ~ 105 ℃
- Package: LQFP64, QFN64, CSP64, QFN56, LQFP48, QFN48, QFN32

Content

1. Introduction

PY32F071 series microcontrollers incorporate high-performance ARM® 32-bit Cortex®-M0+ core, wide operating range voltage, embedded memories with up to 128 Kbytes flash and 32 Kbytes SRAM, frequency up to 72 MHz, and contains various products in different package types. The chip integrates multi-channel I^2C, SPI, USART and other communication peripherals, one 12-bit ADC, two DAC, 13 timers, one USB 2.0, three comparators, three operational amplifiers, and one LCD driver.

PY32F071 series microcontrollers ’s operate in the temperature range from -40 to 85°C or -40 to 105°C, and with operating voltages from 1.7 to 5.5 V. The chip provides sleep and stop low-power operating modes, which can meet different low-power applications.

The devices are suitable for various application scenarios, such as controllers, portable devices, PC peripherals, gaming and GPS platforms, industrial applications.

Table 1-1 PY32F071x6 series device features and peripheral counts

Peripherals		PY32F071R1 BT6	PY32F071R1 BU6	PY32F071R1 BY6	PY32F071P1 BU6	PY32F071C1 BT6	PY32F071C1 8T6	PY32F071C1 BU6	PY32F071K1 BU6	PY32F071K1 8U6
Flash (Kbytes)		128	128	128	128	128	64	128	128	64
SRAM (Kbytes)		16	16	16	16	16	8	16	16	8
Timers	Advanced	1 (16-bit)								
	General pupose	5 (16-bit)								
		1(32-bit)								
	Basic	2								
	low power	1								
	SysTick	1								
	Watchdog	2								
Comm. interfaces	SPI[I^2S]	2[2]								
	I^2C	2								
	USART	4								
	USB	1								
DMA		7ch								
RTC		Yes								
GPIOs		58	58	54	54	42	42	42	28	28
ADC (external + internal)		1 (16 + 8)	1 (16 + 8)	1 (16 + 8)	1 (16 + 8)	1 (10 + 8)	1 (10 + 8)	1 (10 + 8)	1 (10 + 8)	1 (10 + 8)
DAC(channels)		2(2)								
Comparators		3								
OPA		3								
LCD Driver		1								

Peripherals	PY32F071R1 BT6	PY32F071R1 BU6	PY32F071R1 BY6	PY32F071P1 BU6	PY32F071C1 BT6	PY32F071C1 8T6	PY32F071C1 BU6	PY32F071K1 BU6	PY32F071K1 8U6
Max. CPU frequency	72 MHz								
Operating Voltage	1.7 - 5.5 V								
Operating Temp.	- 40 ~ 85 °C								
Package	LQFP64	QFN64	CSP64	QFN56	LQFP48	LQFP48	QFN48	QFN32	QFN32

Table 1-2 PY32F071x7 series device features and peripheral counts

Peripherals		PY32F071C1BT7
Flash (Kbytes)		128
SRAM (Kbytes)		16
Timers	Advanced	1 (16-bit)
	General pupose	5 (16-bit)
		1(32-bit)
	Basic	2
	low power	1
	SysTick	1
	Watchdog	2
Comm. interfaces	SPI[I^2S]	2[2]
	I^2C	2
	USART	4
	USB	1
DMA		7ch
RTC		Yes

Peripherals	PY32F071C1BT7
GPIOs	42
ADC (external + internal)	1 (10 + 8)
DAC(channels)	2(2)
Comparators	3
OPA	3
LCD Driver	1
Max. CPU frequency	72 MHz
Operating Voltage	1.7 ~ 5.5 V
Operating Temp.	- 40 ~ 105 °C
Package	LQFP48

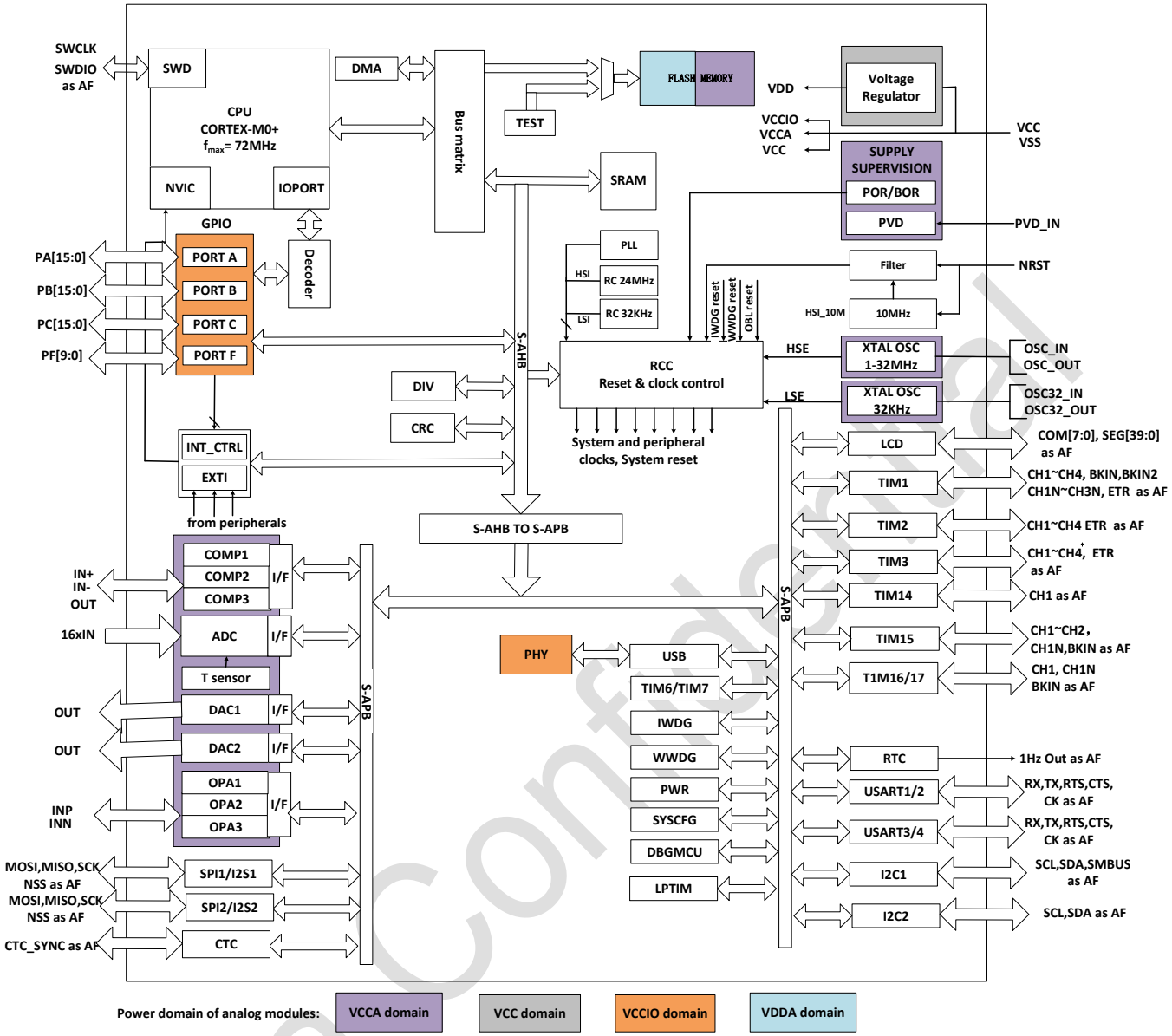


Figure 1-1 System block diagram

2. Functional Overview

2.1. Arm®-Cortex®-M0+ core

The Arm® Cortex® -M0+ is an entry-level Arm 32-bit Cortex processor designed for a wide range of embedded applications. It provides developers with significant benefits, including:

- Simple structure, easy to learn and program
- Ultra-low power consumption, energy-saving operation
- Reduced code density and more

Cortex-M0+ processor is a 32-bit core optimized for area and power consumption and is a 2-stage pipeline Von Neumann architecture. The processor offers high-end processing hardware, including single-cycle multipliers, through a streamlined but powerful instruction set and an extensively optimized design. Moreover, it delivers the superior performance expected from a 32-bit architecture computer, with a higher coding density than other 8 and 16-bit microcontrollers.

The Cortex-M0+ is tightly coupled with a Nested Vectored Interrupt Controller (NVIC).

2.2. Memories

The on-chip integrated SRAM is accessed by bytes (8 bits), half-word (16 bits) or word (32 bits).

The on-chip integrated Flash consists of two different physical areas:

- Main flash area contains application and user data
- Information area has 14 Kbytes, and it includes the following parts:
  - Option bytes
  - UID bytes
  - System memory

The protection of Flash main memory includes the following mechanisms:

- Read protection (RDP) prevents outside access.
- Wrtie protection (WRP) prevents unwanted write operation (confuse by program memory pointer from PC). The minimum protection unit for write protection is 8 Kbytes .
- Option byte write protection is a special design for unlock.

2.3. Boot modes

At startup, the BOOT0 pin and boot selector option bit nBOOT are used to select one of the three boot options in the following table:

Table 2-1 Boot configuration

Boot mode configuration		Mode
nBOOT1 bit	BOOT0 pin	
X	0	Main Flash as the boot area
1	1	System memory as the boot area
0	1	SRAM as the boot area

The Boot loader is located in the System memory and is used to download the Flash program through the USART interface.

2.4. Clock system

At startup, the default system clock frequency is HSI 8 MHz, and after the program is operating the system clock frequency and system clock source can be reconfigured. The high frequency clocks that can be selected are:

- A 4/8/16/22.12/24 MHz configurable internal high precision HSI clock
- A 32.768 kHz configurable internal LSI clock
- A 4 to 32 MHz HSE clock, and used to enable the CSS function to detect HSE. If CSS fails, the hardware will automatically convert the system clock to HSI, and software configures the HSI frequency. Simultaneously, CPU NMI interrupt is generated.
- A 32.768 kHz LSE clock.
- PLL clock has HSI and HSE sources. If the HSE source is selected, when CSS is enabled and CSS fails, the PLL and HSE will be turned off, and the hardware selects the system clock source as HSI.

The AHB clock can be divided based on the system clock, and the APB clock can be divided based on the AHB clock. AHB and APB clock frequencies up to 72 MHz.

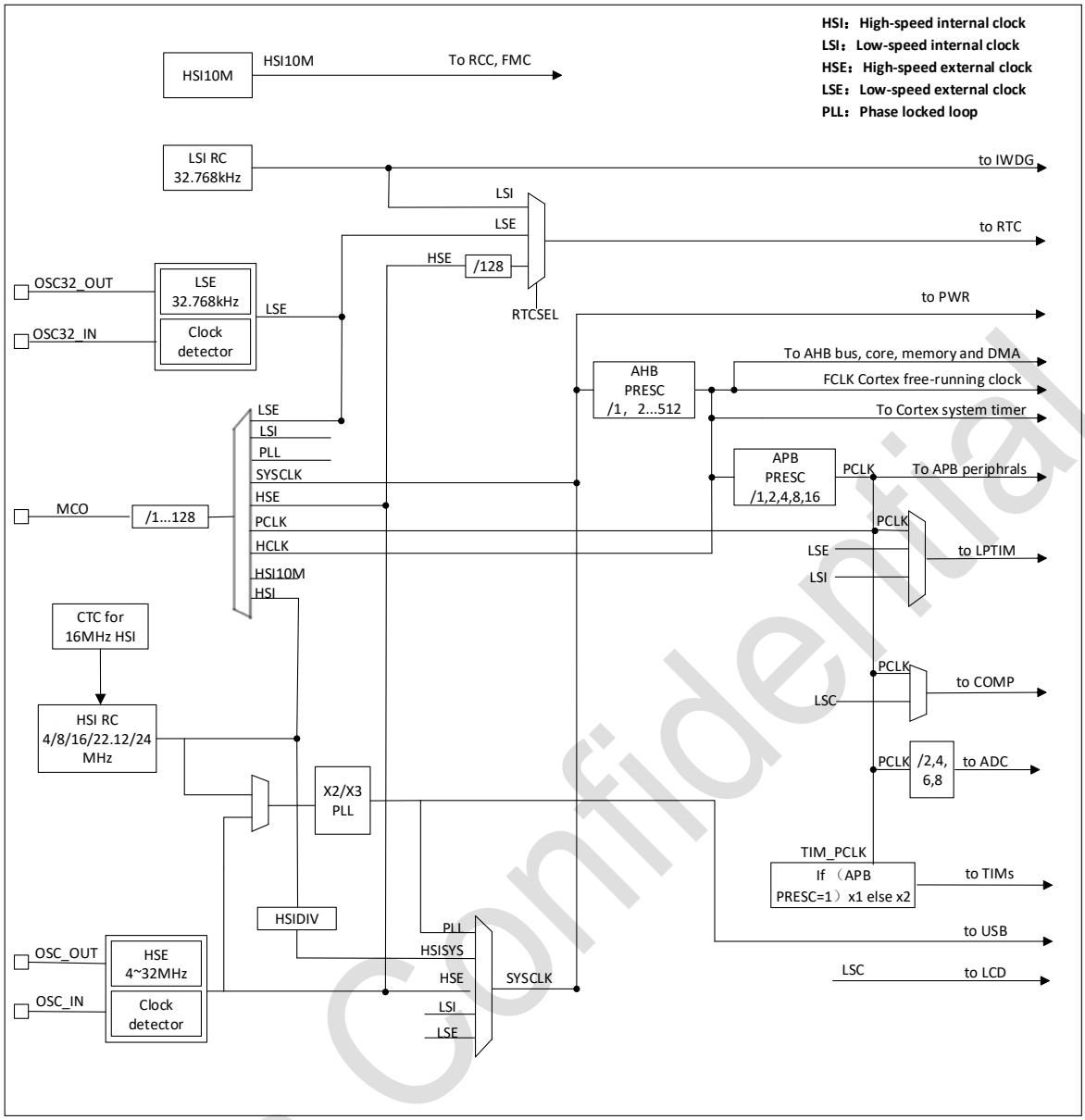


Figure 2-1 System Clock Structure Diagram

2.5. Power management

2.5.1. Power block diagram

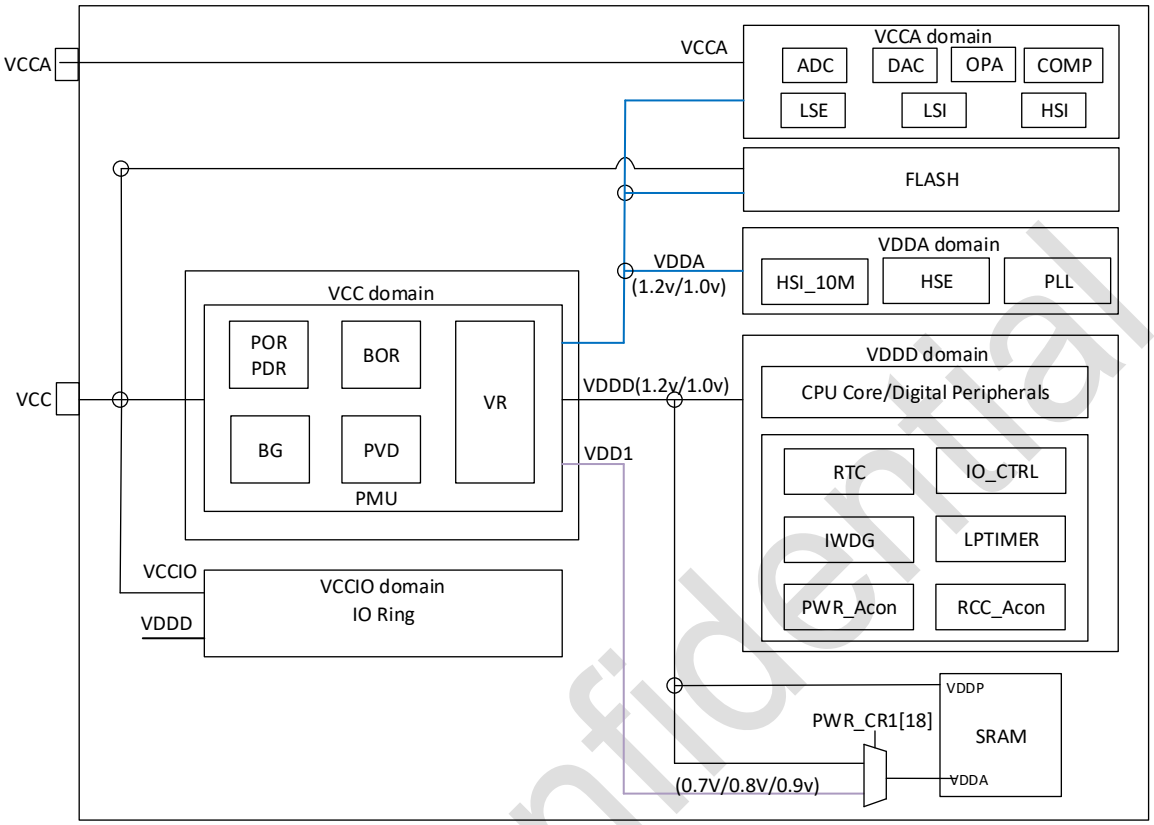


Figure 2-2 Power block diagram

Table 2-2 Power Block Diagram

No.	Power supply	Power value	Describe
1	V_{CC}	1.7 to 5.5 V	The chip is supplied power through the power pins.
2	V_{DDD}	1.2/1.0 V ± 10 %	VR supplies power to the main logic circuits and SRAM inside the chip. When the MR is powered, it outputs 1.2 V. According to the software configuration, when entering the stop mode it powered by MR or LPR, and the LPR output is determined to be 1.2 V or 1.0 V.
3	V_{CCA}	1.7 to 5.5 V	The chip is supplied analog power through the power pins.

2.5.2. Power monitoring

2.5.2.1. Power on reset (POR/PDR)

The power-on reset (POR) and power-down reset (PDR) module is designed in the chip to provide power-on and power-off reset for the chip. The module keeps working in all modes.

2.5.2.2. Brown-out reset (BOR)

In addition to POR/ PDR, BOR (brown-out reset) is also implemented. BOR can only be enabled and disabled through the option byte .

When the BOR is turned on, the BOR threshold can be selected by the Option byte, and both the rising and falling detection points can be configured individually.

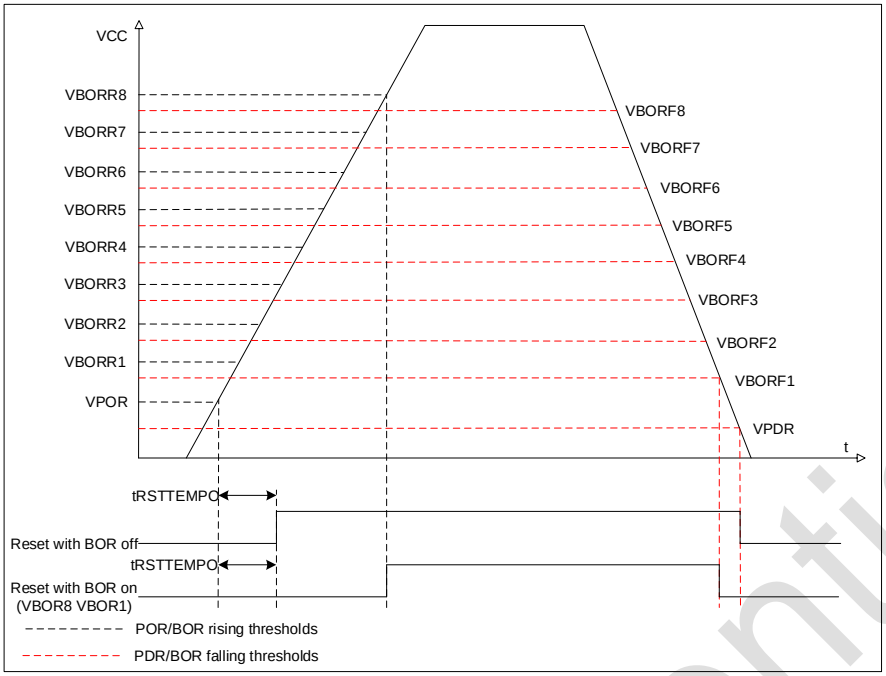


Figure 2-3 POR/PDR/BOR threshold

2.5.2.3. Programmable voltage detection (PVD)

Programmable voltage detector (PVD) module can be used to detect the V_{CC} power supply and the voltage of the PB7 pin, and the detection point is configured through the register. When V_{CC} is higher or lower than the detection point of PVD , the corresponding reset flag is generated.

This event is internally connected to line 16 of EXTI , depending on the rising/falling edge configuration of EXTI line 16, when V_{CC} rises above the detection point of PVD, or V_{CC} falls below the detection point of PVD, an interrupt is generated. In the service program, users can perform urgent shutdown tasks.

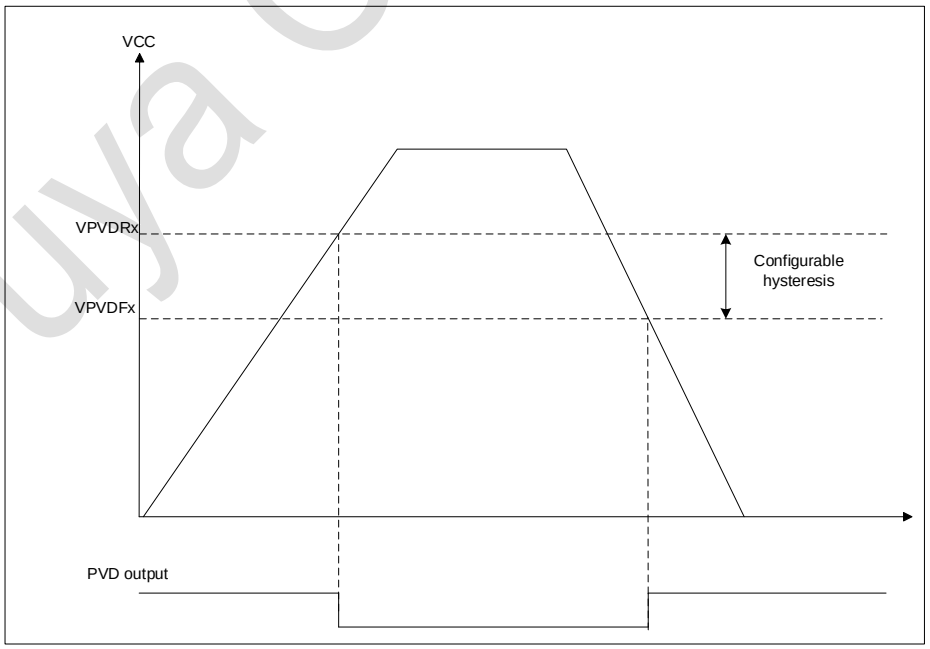


Figure 2-4 PVD threshold

2.5.3. Voltage regulator

The regulator has two operating modes:

- Main regulator (MR) is used in normal operating mode.
- Low power regulator (LPR) can be used in Stop mode where the power demand is reduced.

2.5.4. Low-power mode

In addition to the normal operating mode, the chip has 2 low-power modes:

- Sleep mode: Peripherals can be configured to keep working when the CPU clock is off (NVIC, SysTick, etc.). It is recommended only to enable the modules that must work, and close the module after the module works.
- Stop mode: In this mode, the contents of SRAM and registers are maintained, HSI and HSE are turned off, and most modules of clocks in the VDD domain are stopped. GPIO, PVD, COMP output, RTC and LPTIM can wake up stop mode.

2.6. Reset

Two resets are designed in the chip: power reset and system reset.

2.6.1. Power reset

A power reset occurs in the following situations:

- Power-on/power-down reset (POR/PDR)
- Brown-out Reset (BOR)

2.6.2. System reset

A system reset occurs when the following events occur:

- Reset of NRST pin
- Windowed watchdog reset (WWDG)
- Independent watchdog reset (IWDG)
- SYSRESETREQ software reset
- Option byte load reset (OBL)
- Power reset (POR/PDR, BOR)

2.7. General-purpose inputs and outputs (GPIOs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as peripheral alternate function, locking mechanism will freeze I/Os configuration function .

2.8. Hardware divider (DIV)

Hardware divider is a 32-bit signed/unsigned integer hardware divider.

DIV feture:

- Configurable signed/unsigned integer division calculation
- 32-bit dividend, 32-bit divisor
- Output 32-bit quotient and 32-bit remainder
- Division zero warning flag, division end flag
- 8 clock cycles to complete a division operation
- Write the divisor register to trigger the division operation to start

- Automatically wait for the end of the calculation when reading the quotient register/remainder register

2.9. Direct memory access controller (DMA)

Direct memory access (DMA) is used to provide high-speed data transfer between peripherals and memory or between memory and memory. Data can be moved quickly through DMA without CPU intervention, which saves CPU resources for other operations. The DMA controller has seven channels, each dedicated to managing requests for memory access from one or more peripherals. There is also a mediator to coordinate the priority of individual DMA requests.

The main functions are as follows:

- Single AHB master
- Support peripherals to memory, the memory to the peripherals, memory to memory and peripherals to peripheral data transmission
- On-chip memory devices, such as FLASH, an SRAM, AHB and APB peripherals, as the source and target
- All DMA channel can be independent configuration:
  - Each channel is associated either with a DMA request signal from a peripheral or with a software trigger in a memory-to-memory transfer. This configuration is done by software.
  - The priority between requests is programmable by software (4 levels per channel: very high, high, medium, low) and, in equal cases, by hardware (such as a request for channel 1 taking precedence over a request for channel 2).
  - The transfer sizes of the source and destination are independent (byte, half word, word), simulating packing and unpacking. The source and destination addresses must be aligned by data size.
  - Programmable data transmission: 0 ~ 65535
- Each channel generates an interrupt request. Each interrupt request is caused by one of three DMA events: transfer completion, half-transfer, or transfer error.

2.10. Interrupts and events

The PY32F071 handles exceptions through the Cortex-M0+ processor's embedded a nested vectored interrupt controller (NVIC) and an extended interrupt/event controller (EXTI).

2.10.1. Nested vectored interrupt controller (NVIC)

NVIC is a tightly coupled IP inside the Cortex-M0+ processor. The NVIC can handle NMI (Non-Maskable Interrupts) and maskable external interrupts from outside the processor and Cortex-M0+ internal exceptions. NVIC provides flexible priority management.

The tight coupling of the processor core to the NVIC greatly reduces the delay between an interrupt event and the initiation of the corresponding interrupt service routine (ISR). The ISR vectors are listed in a vector table, stored at a base address of the NVIC. The vector table base address determines the vector address of the ISR to execute, and the ISR is used as the offset composed of serial numbers.

If a high-priority interrupt event occurs and a low-priority interrupt event is just waiting to be serviced, the later-arriving high-priority interrupt event will be serviced first. Another optimization is called tail-chaining. When returning from a high-priority ISR and then starting a pending low-priority ISR, unnecessary pushes and pops of processor contexts will be skipped. This reduces latency and improves power efficiency.

NVIC features:

- Low latency interrupt handling
- Level 4 interrupt priority
- Supports one NMI interrupt
- Support 32 maskable external interrupts
- Supports 10 Cortex-M0+ exceptions
- High-priority interrupts can interrupt low-priority interrupt responses
- Support tail-chaining optimization
- Hardware interrupt vector retrieval

2.10.2. Extended interrupt/event controller (EXTI)

EXTI adds flexibility to handle physical wire events and generates wake-up events when the processor wakes up from stop mode.

The EXTI controller has multiple channels, including a maximum of 16 GPIOs, 1 PVD output, 3 COMP outputs, RTC and LPTIM wake-up signals. GPIO, PVD and COMP can be configured to be triggered by a rising edge, falling edge or double edge. Any GPIO signal can be configured as EXTI0 to 15 channel through the select signal.

- Each EXTI line can be independently masked through registers.
- The EXTI controller can capture pulses shorter than the internal clock period.
- Registers in the EXTI controller latch each event. Even in stop mode, after the processor wakes up from stop mode, it can identify the wake-up source or identify the GPIO and event that caused the interrupt.

2.11. Analog-to-digital converter (ADC)

The chip has a 12-bit SARADC. The module has up to 24 channels to be measured, including 16 external channels and 8 internal channels. The reference voltage can be selected with precision voltage (1.5 V, 2.048 V or 2.5 V) or the power supply voltage.

- The conversion mode of each channel can be set to single, continuous, sweep, discontinuous mode. Conversion results are stored in left or right-aligned 16-bit data registers.
- An analogue watchdog allows the application to detect if the input voltage exceeds a user-defined high or low threshold.
- The ADC has been implemented to operate at a low frequency, resulting in lower power consumption.

- At the end of sampling, conversion, and continuous conversion, an interrupt request is generated when the conversion voltage exceeds the threshold when simulating the watchdog.

2.12. Digital-to-analog converter (DAC)

Digital/analog conversion module (DAC) is a 12-bit digital input, voltage output digital/analog converter. The DAC can be configured in 8-bit or 12-bit mode, or can be used in conjunction with a DMA controller. When the DAC is operating in 12-bit mode, the data can be left justified or right justified. The DAC module has two output channels, each with a separate converter. In dual-DAC mode, the two channels can be converted independently, or they can be converted simultaneously and update the output of the two channels synchronously. The main features are as follows:

- 12 mode data left or right aligned
- synchronous update functionality
- waveform generating noise
- triangle waveform generation
- dual DAC channel or respectively at the same time
- each channel has the DMA function
- support DMA underflow error detection
- external triggers the transformation

2.13. Comparators (COMP)

Three general purpose comparators are integrated in the chip, namely COMP1/2/3. These two or three modules can be used as separate modules or combined with timer.

Comparators can be used as follows:

- Triggered by analog signal to generate low-power mode wake-up function
- Analog signal conditioning
- Cycle by cycle current control loop when connected with PWM output from timer

2.14. Operational amplifier (OPA)

The OPA1/2/3 module can be flexibly configured and is suitable for simple amplifiers. The three internal opamps can be cascaded using external resistors.

OPA features are summarized as follows:

- Three independently configured operational amps
- OPA input range is 0 to AV_{CC}, output range is 0.1 V to AV_{CC} - 0.2 V (demand) to simulate a module, a programmable gain
- Can be configured for the following models
- General operational mode (general purpose OPA)
- DAC voltage follower

2.15. Liquid crystal display (LCD) controller

The LCD controller is a digital controller/driver for monochrome passive liquid crystal displays (LCDS), with up to 8 common terminals (COM) and 40 segment terminals (SEG) to drive 160 (4 * 40) or 288 (8

* 36) LCD image elements. The exact number of terminals depends on the device pins described in the data manual. LCD functions are summarized as follows:

- Highly flexible frame rate control
- Support static, 1/2, 1/3, 1/4, 1/6, and 1/8 of a duty ratio
- Support 1/2, 1/3 bias voltage
- Up to 16 registers LCD data RAM
- By software configuration of LCD contrast
- 3 kinds of waveform generation
  - internal resistance pressure resistance, external pressure, external capacitance partial pressure
  - by way of internal resistance of the software configuration partial pressure power consumption, so as to match the capacitance charge needed for the LCD panel
- Support low power consumption modes: LCD controller can be on the run, Sleep and stop mode for display
- Configurable frame interrupt
- Support LCD flashing function and configuration of multiple flicker frequency
- Unused LCD segments and public pin can be configured to digital or analog functions

2.16. Timer

The characteristics of different timers of PY32F071 series are shown in the following table:

Table 2-3 Timer features comparsion

Type	Timer	Counter resolution	Counter type	Prescaler factor	DMA	Capture /compare channels	Comple-mentary outputs
Advanced control	TIM1	16-bit	Up, down, center aligned	Integer from 1 to 65536	Support	4	3
General purpose	TIM2	32-bit	Up, down, center aligned	Integer from 1 to 65536	Support	4	-
General purpose	TIM3	16-bit	Up, down, center aligned	Integer from 1 to 65536	Support	4	-
	TIM14	16-bit	Up	Integer from 1 to 65536	-	1	-
	TIM15	16-bit	Up	Integer from 1 to 65536	-	2	1
	TIM16, TIM17	16-bit	Up	Integer from 1 to 65536	Support	1	1
Basic	TIM6, TIM7	16-bit	Up	Integer from 1 to 65536	Support	-	-

2.16.1. Advanced-control timer (TIM1)

The advanced-control timer (TIM1) is consist of a 16-bit auto-reload counter driven by a programmable prescaler. It can be used in various scenarios, including pulse length measurement of input signals (input capture) or generating output waveforms (output compare, output PWM, complementary PWM with dead-time insertion).

TIM1 includes 4 independent channels:

- Input capture
- Output comparison
- PWM generation (edge or center-aligned mode)
- Single pulse mode output

If TIM1 is configured as a standard 16-bit timer, it has the same features as the TIMx timer. If configured as the 16-bit PWM generator, it has full modulation capability (0-100%).

The counter can can be frozen in debug mode.

Many features are shared with those of the standard timers which have the same architecture. The advanced control timer can therefore work together with the other timers by the Timer Link feature for synchronization or event chaining.

TIM1 supports the DMA function.

2.16.2. General-purpose timers

2.16.2.1. TIM2/TIM3

The general-purpose timers TIM2/TIM3 are consist of 32/16-bit auto-reload counters and a 32/16-bit prescaler. There are four independent channels each for input capture/output compare, PWM or one-pulse mode output.

- They can work with the TIM1 by the Timer Link.
- TIM2/TIM3 supports DMA function.
- This timer is capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 3 hall-effect sensors.
- The counter can be frozen in debug mode.

2.16.2.2. TIM14

- The general-purpose timer (TIM14) is consist of a 16-bit auto-reload counter driven by a programmable prescaler.
- TIM14 features one single channel for input capture/output compare, PWM or one-pulse mode output.
- The counter can be frozen in debug mode.

2.16.2.3. TIM15/TIM16/TIM17

- The general-purpose timer (TIM15, TIM16 and TIM17) is consist of a 16-bit auto-reload counter driven by a programmable prescaler.
- TIM16/TIM17 features one single channel for input capture/output compare, PWM or one-pulse mode output.
- TIM15 features two single channel for input capture/output compare, PWM or one-pulse mode output.
- TIM15/TIM16/TIM17 have complementary outputs with dead time.
- TIM15/TIM16/TIM17 supports DMA function.
- The counter can be frozen in debug mode.

2.16.3. Basic timers (TIM6/TIM7)

- The basic timer (TIM6/TIM7) is consist of a 16-bit auto-reload upcounter driven by their programmable prescaler respectively.
- Synchronization circuit to trigger DAC.
- Generate interrupt/DMA request on update event (counter overflow).

2.16.4. Low power timer (LPTIM)

- LPTIM is a 16 -bit upcounter with a 3-bit prescaler and only support a single count.
- LPTIM can be configured as a stop mode wake-up source.
- The counter can be frozen in debug mode.

2.16.5. Independent watchdog (IWDG)

Independent watchdog (IWDG) is integrated in the chip, and this module has the characteristics of high-security level, accurate timing and flexible use. IWDG finds and resolves functional confusion due to software failure and triggers a system reset when the counter reaches the specified timeout value.

- The IWDG is clocked by LSI, so even if the main clock fails, it can keep working.
- IWDG is the best suited for applications that require the watchdog as a standalone process outside of the main application and do not have high timing accuracy constraints.
- Controlling of option byte can enable IWDG hardware mode.
- IWDG is the wake-up source of stop mode, which wakes up stop mode by reset.
- The counter can be frozen in debug mode.

2.16.6. System window watchdog (WWDG)

The system window watchdog is based on a 7-bit downcounter that can be set as free running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the APB clock (PCLK). It has an early warning interrupt capability, and the counter can be frozen in debug mode.

2.16.7. SysTick timer

SysTick timer is dedicated to real-time operating systems, but could also be used as a standard downcounter.

SysTick Features:

- 24-bit down counter
- Auto-reload capability
- Maskable system interrupt generation when the counter reaches 0

2.17. Real-time clock (RTC)

The real-time clock is an independent counter. It has a set of continuous counting counters, which can provide a clock calendar function under the corresponding software configuration. Modifying the value of the counter can reset the current time and date of the system.

- RTC is a 32-bit programmable counter with a prescale factor of up to 2^{20} bits.
- The RTC counter clock source can be LSE/LSI and the stop wake-up source.
- RTC can generate alarm interrupt, second interrupt and overflow interrupt (maskable).

- RTC supports clock calibration.
- RTC can be frozen in debug mode.

2.18. Cyclic redundancy check cell(CRC)

CRC computing unit is based on a fixed generation polynomial to obtain 32-bit CRC computing results. In other applications, CRC technology is mainly used to verify the correctness and integrity of data transmission or data storage. CRC cell contains one 32-bit data register:

- When writing to this register, as an input register, you can enter new data to perform CRC calculations.
- When the register is read, the result of the last CRC calculation is returned.
- Each time a data register is written, the result of the calculation is a combination of the previous CRC calculation and the new calculation (CRC calculation is performed on the entire 32-bit word rather than byte by byte).
- You can RESET register CRC_DR to 0xFFFF by setting the reset bit of register CRC_CR. This operation does not affect the data in register CRC_IDR.
- The initial CRC value can be configured.

2.19. Clock check system (CTC)

The clock calibration controller (CTC) uses hardware to automatically calibrate the RC crystal oscillator (HSI) when the internal configuration is 16 MHz, and uses the PLL (48 M) after 3 times the frequency as the clock source of the USBD module. The CTC module calibrates the HSI clock frequency based on an external high-precision reference signal source, and adjusts the calibration value automatically or manually to obtain an accurate PLL 48 M clock.

The CTC module performs the following functions:

- Three external reference sources: GPIO, LSE clock,USBD_SOF.
- Provide software reference synchronization pulse.
- Hardware calibration automatically, no software operation.
- 16 bits calibration counter with reference source capture and overload capabilities.
- 8 bits clock calibration base value for frequency evaluation and automatic calibration.
- Flag bits and interrupts that indicate the state of clock calibration: calibration success state (CKOKIF), Warning state (CKWARNIF), and error state (ERRIF).

2.20. System configuration controller (SYSCFG)

The SYSCFG module provides the following functions:

- The filtering function on the IO pin of the _I^2C type was enabled or disabled
- Enable or disable filtering on all I/O pins
- Remap trigger sources for some Dmas to different DMA channels
- Remap memory at the beginning of the code interval (Boot)
- Manages the TIMERs ETR or brake input

2.21. Debug support (DBG)

The MCU DBG module assists the debugger with the following functions:

- Support sleep mode, stop mode and standby mode
- When the CPU enters the HALT mode, the control timer or watchdog stops counting or continues counting
- Block I²C1 and I²C2 SMBUS timeouts when the CPU is in HALT mode
- Assign tracking pins

The MCUDBG register also provides chip ID encoding. This ID encoding can be accessed by a JTAG or SW debug interface, or by a user program.

2.22. Inter-integrated circuit interface (I²C)

I²C (inter-integrated circuit) bus interface connects the microcontroller and the serial I²C bus. It provides multi-master capability and controls all I²C bus specific sequences, protocols, arbitration and timing. Standard mode (Sm) and fast mode (Fm) are supported.

I²C Features:

- Two I²C Interface, support slave and master mode
- Multi-host function : can be master or slave
- Support different communication speeds
  - Standard Mode (Sm): Up to 100 kHz
  - Fast Mode (Fm): up to 400 kHz
- As master
  - Generate Clock
  - Generation of Start and Stop
- As slave
  - Programmable I²C address detection
  - Dual-address capability that responds to two secondary addresses
  - Discovery of the Stop bit
- 7-bit/10-bit addressing mode
- General call
- Status flag
  - Transmit/receive mode flags
  - Byte transfer complete flag
  - I²C busy flag bit
- Error flag
  - Master a rbitration loss
  - ACK failure after address/data transfer
  - Start/Stop error
  - Overrun/Underrun (clock stretching function disable)
- Optional clock stretching
- Single-byte buffer with DMA capability

- Software reset
- Analog noise filter function
- Support SMBus

2.23. Universal synchronous/asynchronous receiver transmitter (USART)

PY32F071 contains 4 USARTs, supports ISO7816, LIN, IrDA.

The USARTs provide a flexible method for full-duplex data exchange with external devices using the industry-standard NRZ asynchronous serial data format. The USART utilizes a fractional baudrate generator to provide a wide range of baudrate options.

It supports simultaneous one-way communication and half-duplex single-wire communication, and it also allows multi-processor communication.

Automatic baudrate detection is supported.

High-speed data communication can be achieved by using the DMA method of the multi-buffer configuration.

USARTs features:

- Full-duplex asynchronous communication
- NRZ standard format
- Configurable 16 times or 8 times oversampling for increased flexibility in speed and clock tolerance
- Programmable baudrate shared by transmit and receive, up to 4.5 Mbit/s
- Automatic baudrate detection
- Programmable data length of 8 or 9 bits
- Configurable stop bits (0.5,1,1 or 2 bits)
- Synchronous mode and clock output function for synchronous communication
- Single-wire half-duplex communication
- Independent transmit and receive enable bits
- Hardware flow control
- Receive/transmit bytes by DMA buffer
- Detection flag
  - Receive full buffer
  - Send empty buffer
  - End of transmission
- Parity control
  - Send check digit
  - Check the received data
- Flagged interrupt sources
  - CTS change
  - Send empty register
  - Send completed
  - Receive full data register

  - Bus idle detected
  - Overflow error
  - Frame error
  - Noise operation
  - Error detection
- Multiprocessor communication
  - If the address does not match, enter silent mode
- Wake-up from silent mode: by idle detection and address flag detection

2.24. Serial peripheral interface (SPI)

PY32F071 contains two SPIs. SPIs allow the chip to communicate with external devices in half-duplex, full-duplex, and simplex synchronous serial communication. This interface can be configured in master mode and provides the communication clock (SCK) for external slave devices. The interface can also work in a multi-master configuration.

The SPI features are as follows:

- Master or slave mode
- 3-wire full-duplex simultaneous transmission
- 2-wire half-duplex synchronous transmission (with bidirectional data line)
- 2-wire simplex synchronous transmission (no bidirectional data line)
- 8-bit or 16-bit transmission frame selection
- Support multi-master mode
- 8 master mode baud rate prescale factors (max $f_{PCLK}/2$)
- Slave mode frequency (max $f_{PCLK}/4$)
- Both master and slave modes can be managed by software or hardware NSS: dynamic change of master/slave operating mode
- Programmable clock polarity and phase
- Programmable data order, MSB first or LSB first
- Dedicated transmit and receive flags that can trigger interrupts
- SPI bus busy status flag
- Motorola mode
- Interrupt-causing master mode faults, overloads
- Two 32-bit Rx and Tx FIFOs with DMA capability

2.25. USB2.0 full-speed module

PY32F071 contains 1 USB 2.0 full speed module. USB peripheral implements the interface between USB2.0 full speed bus and APB1 bus. Support USB suspend/restore operation, can stop the device clock to achieve low power consumption. The main features are as follows:

- Comply with the technical specifications of USB 2.0 full speed devices
- It can be configured with 1 to 6 USB endpoints
- CRC(cyclic redundancy check) generation/check, reverse non-return to zero (NRZI) encoding/decoding and bit filling

- Support control transmission/synchronous transmission/batch transmission/interrupt transmission
- Supports a dual buffer mechanism for batch/synchronous endpoints
- USB suspend and restore operations are supported
- Frame lock clock pulse generation
- Dedicated 1024-byte packet cache storage

2.26. Serial wire debug (SWD)

The ARM SWD interface allows serial debugging tools to be connected to the PY32F071.

3. Pin Configuration

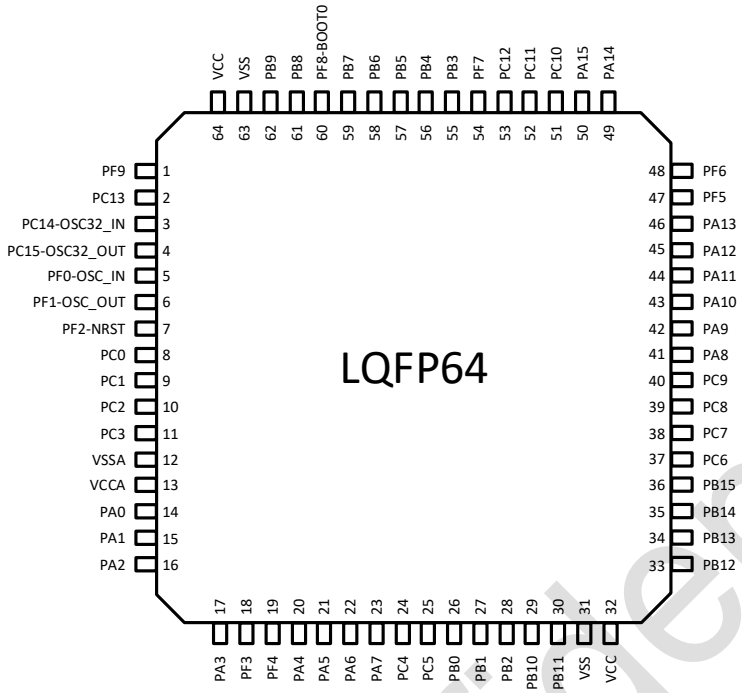


Figure 3-1 LQFP64 PY32F071R1xT6 Pinout1(Top view)

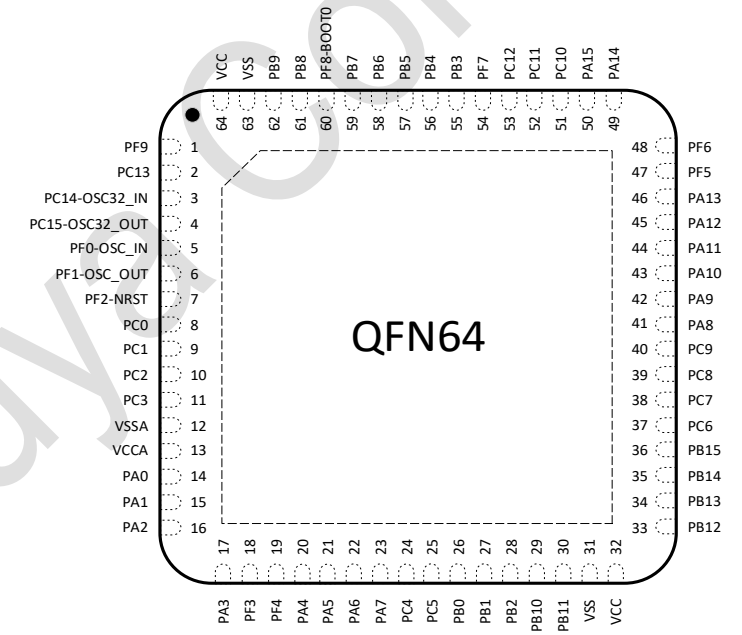


Figure 3-2 QFN64 PY32F071R1xU6 Pinout1(Top view)

	A	B	C	D	E	F	G	H
1	PA8	PA13	PF7	PB3	PB5	PF8	PB8	PF9
2	PA9	VSS	PC11	PC12	PB7	VSS	PB9	PC13
3	PA11	PA12	VCC	PB4	PB6	VCC	PC14	PC15
4	PC9	PA10	PA14	PA15	PC10	PF2	PF1	PF0
5	PC8	PC7	PB10	PC4	PC1	VSSA	PC3	PC0
6	PC6	PB13	PB11	PB0	PA0	PA2	VCCA	PC2
7	PB15	VCC	VSS	PB2	PA7	VCC	VSS	PA1
8	PB14	PB12	PB1	PC5	PA6	PA5	PA4	PA3

Figure 3-3 CSP64 PY32F071R1xY6 Pinout1(Top view)

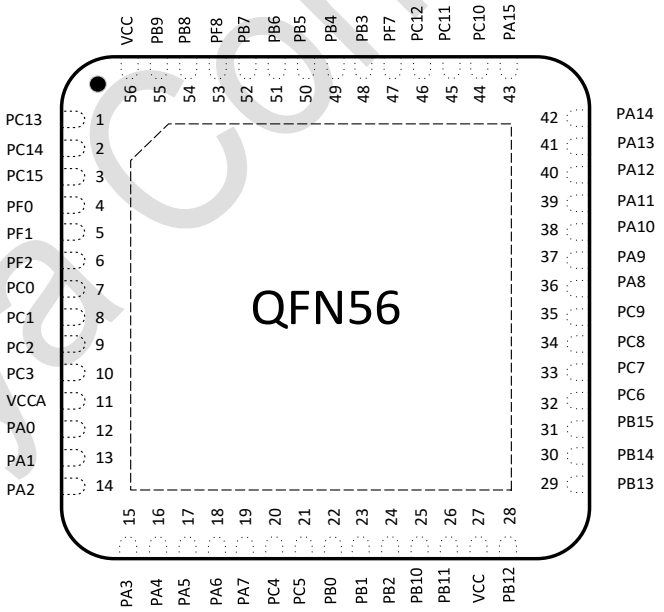


Figure 3-4 QFN56 PY32F071P1xU6 Pinout1(Top view)

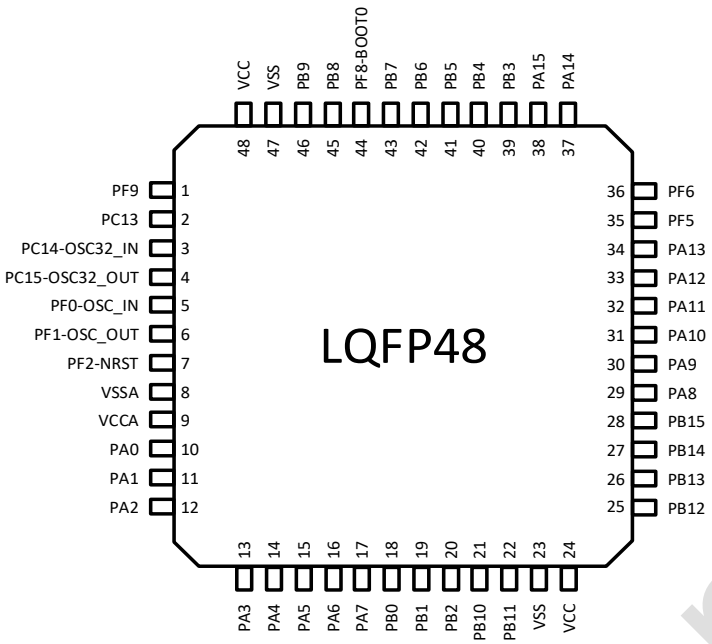


Figure 3-5 LQFP48 PY32F071C1xTx Pinout1(Top view)

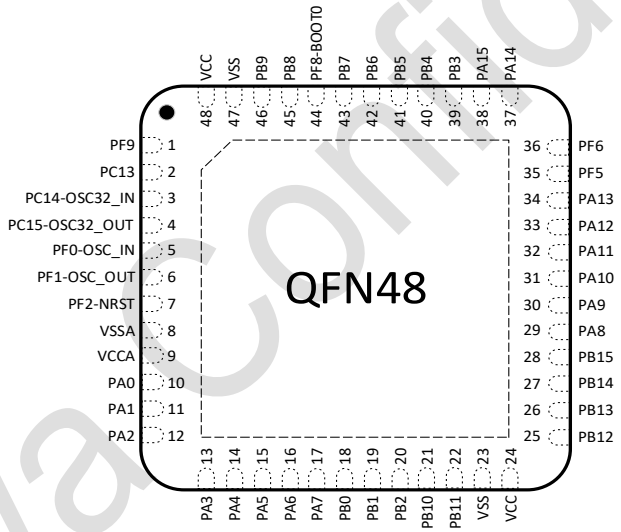


Figure 3-6 QFN48 PY32F071C1xU6 Pinout1(Top view)

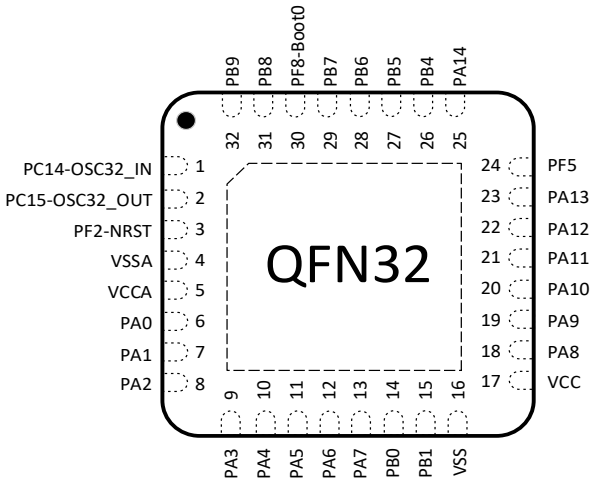


Figure 3-7 QFN32(5*5) PY32F071K1xU6 Pinout1(Top view)

Table 3-1 Pin Definition Terminology and Symbols

Name		Symbol	Definition
Pin type		S	Supply pin
		G	Ground pin
		I	Input-only pin
		I/O	Input/output pin
I/O structure		COM	Normal 5V I/O with analog input and output function
		RST	Reset pin, with internal weak pull-up resistor, without analog input and output function
		COM_F	I/O, I^2C Fm+ capable with analog input and output function
		COM_U	GPIO 5V tolerant with USB PHY function
Notes		-	Unless otherwise specified, all ports are used as floating inputs between and after reset
Pin function	Alternate functions	-	Function selected by GPIOx_AFR register
	Additional functions	-	Directly selected or enabled through peripheral registers

Table 3-2 Pin definition

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
1	H1	1	1	-	1		PF9	I/O	COM		-	-
2	H2	2	2	1	2		PC13	I/O	COM		SPI1_SCK/I²S1_CK	-
											TIM1_BKIN	
3	G3	3	3	2	3	1	PC14	I/O	COM		TIM1_BKIN2	OSC32_IN
4	H3	4	4	3	4	2	PC15	I/O	COM		TIM15_BKIN	OSC32_OUT
5	H4	5	5	4	5	-	PF0-OSC_IN	I/O	COM		CTC_SYNC	OSC_IN
											USART2_TX	
											TIM1_BKIN	
											TIM14_CH1	
6	G4	6	6	5	6	-	PF1-OSC_OUT	I/O	COM		USART2_RX	OSC_OUT
											TIM1_CH1N	
											TIM15_CH1N	
7	F4	7	7	6	7	3	PF2-NRST	I/O	RST	(1)	TIM1_CH2	-
											EVENTOUT	
											MCO	
8	H5	-	8	7	-	-	PC0	I/O	COM		EVENTOUT	ADC_IN10, COMP1_INP0, COMP2_INN0, SEG27
											SPI1_MISO/I²S1_MCK	
											USART2_CTS	
											USART3_RTS	
9	E5	-	9	8	-	-	PC1	I/O	COM		EVENTOUT	ADC_IN11, COMP1_INP1, COMP2_INN1, SEG26
											SPI1_MOSI/I²S1_SD	
											USART2_RTS	
											USART3_CTS	

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											TIM15_CH1	
10	H6	-	10	9	-	-	PC2	I/O	COM		EVENTOUT SPI2_MISO/I²S2_MCK USART3_TX USART3_RX TIM15_CH2	ADC_IN12, COMP1_INP2, COMP2_INN2, SEG25
11	G5	-	11	10	-	-	PC3	I/O	COM		EVENTOUT SPI2_MOSI/I²S2_SD USART3_RX USART3_TX	ADC_IN13, COMP1_INP3, COMP2_INN3, SEG24
12	F5	8	12	-	8	4	V_{SSA}	G			Ground	
13	G6	9	13	11	9	5	V_{CCA}	S			Analog power supply	
14	E6	10	14	12	10	6	PA0	I/O	COM		USART2_CTS TIM2_CH1_ETR USART4_TX COMP1_OUT SPI2_SCK	ADC_IN0, COMP1_INP4, COMP1_INN0, COMP2_INP0, COMP2_INN4, SEG23
15	H7	11	15	13	11	7	PA1	I/O	COM		EVENTOUT USART2_RTS TIM2_CH2 USART4_RX TIM15_CH1N I²C1_SMBA SPI1_SCK/I²S1_CK	ADC_IN1, COMP1_INP5, COMP1_INN1, COMP2_INP1, COMP2_INN5, SEG22

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											SPI2_MOSI	
16	F6	12	16	14	12	8	PA2	I/O	COM		TIM15_CH1 USART2_TX TIM2_CH3 COMP2_OUT SPI1_MOSI/I²S1_SD SPI2_MISO	ADC_IN2, COMP1_INP6, COMP1_INN2, COMP2_INP2, SEG21
17	H8	13	17	15	13	9	PA3	I/O	COM		EVENTOUT TIM15_CH2 USART2_RX TIM2_CH4 SPI2_MISO SPI2_NSS/I²S2_WS	ADC_IN3, COMP1_INP7, COMP1_INN3, COMP2_INP3, SEG20
18	-	-	18	-	-	-	PF3	I/O	COM_F		EVENTOUT I²C1_SCL I²C2_SCL	-
19	-	-	19	-	-	-	PF4	I/O	COM_F		I²C1_SCL I²C2_SCL	-
20	G8	14	20	16	14	10	PA4	I/O	COM		EVENTOUT SPI1_NSS/I²S1_WS USART2_CK TIM14_CH1 SPI2_MOSI USART2_TX	ADC_IN4, DAC_OUT1, COMP1_INP8, COMP1_INN4, COMP2_INP4, SEG19

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											PVD_OUT	
21	F8	15	21	17	15	11	PA5	I/O	COM		EVENTOUT	ADC_IN5, DAC_OUT2, COMP1_INP9, COMP1_INN5, COMP2_INP5, COMP3_INP0, COMP3_INN0, SEG18, OPA2_OUT
											SPI1_SCK/ I²S1_CK	
											TIM2_CH1_ETR	
											USART3_TX	
22	E8	16	22	18	16	12	PA6	I/O	COM		EVENTOUT	ADC_IN6, COMP1_INP10, COMP1_INN6, OPA2_INN, SEG17
											SPI1_MISO/I²S1_MCK	
											TIM3_CH1	
											TIM1_BKIN	
											USART3_CTS	
											TIM16_CH1	
											COMP1_OUT	
23	E7	17	23	19	17	13	PA7	I/O	COM		EVENTOUT	ADC_IN7, COMP1_INP11, COMP1_INN7, OPA2_INP, SEG16
											SPI1_MOSI/I²S1_SD	
											TIM3_CH2	
											TIM1_CH1N	
											TIM14_CH1	
											TIM17_CH1	
											COMP2_OUT	
24	D5	-	24	20	-	-	PC4	I/O	COM		EVENTOUT	ADC_IN14, COMP1_INN8,
											USART3_TX	

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											COMP3_OUT	SEG15
											SPI1_NSS/I²S1_WS	
											USART1_TX	
											TIM2_CH1_ETR	
											IR_OUT	
25	D8	-	25	21	-	-	PC5	I/O	COM		USART3_RX	ADC_IN15, COMP1_INN9, SEG14
											SPI1_MOSI/I²S1_SD	
											USART1_RX	
											TIM2_CH2	
26	D6	18	26	22	18	14	PB0	I/O	COM		EVENTOUT	ADC_IN8, COMP2_INN6, SEG13
											TIM3_CH3	
											TIM1_CH2N	
											USART3_CK	
											COMP1_OUT	
											SPI1_NSS/I²S1_WS	
											USART3_RX	
27	C7	19	27	23	19	15	PB1	I/O	COM		EVENTOUT	ADC_IN9, COMP2_INP6, COMP2_INN7, COMP3_INP1, COMP3_INN1, SEG12
											TIM14_CH1	
											TIM3_CH4	
											TIM1_CH3N	
											USART3_RTS	
											COMP3_OUT	
28	D7	20	28	24	20	-	PB2	I/O	COM		EVENTOUT	COMP2_INP7, COMP2_INN8,
											SPI2_MISO	

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											USART3_TX	SEG11
29	C5	21	29	25	21	-	PB10	I/O	COM_F		I²C2_SCL	COMP2_INP8, SEG10
											TIM2_CH3	
											USART3_TX	
											SPI2_SCK/I²S2_CK	
											COMP1_OUT	
											USART2_RTS	
											I²C1_SCL	
30	C6	22	30	26	22	-	PB11	I/O	COM_F		EVENTOUT	COMP3_INP8, COMP3_INN4, SEG9
											I²C2_SDA	
											TIM2_CH4	
											USART3_RX	
											COMP2_OUT	
											SPI2_MOSI	
											USART2_CTS	
											I²C1_SDA	
31	B2	23	31	-	23	16	V_{SS}	G			Ground	
32	B7	24	32	27	24	17	V_{CC}	S			Digital power supply	
33	B8	25	33	28	25	-	PB12	I/O	COM		EVENTOUT	COMP2_INP9, OPA3_INN, SEG8
											SPI2_NSS/I²S2_WS	
											TIM1_BKIN	
											USART3_CK	
											TIM15_BKIN	
34	B6	26	34	29	26	-	PB13	I/O	COM_F		EVENTOUT	COMP2_INP10,

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											SPI2_SCK/I²S2_CK	OPA3_INP, SEG7
											TIM1_CH1N	
											USART3_CTS	
											I²C2_SCL	
											MCO	
											TIM15_CH1N	
											I²C1_SCL	
35	A8	27	35	30	27	-	PB14	I/O	COM_F		EVENTOUT	COMP2_INP11, COMP3_INP9, COMP3_INN5 OPA3_OUT SEG6
											SPI2_MISO/I²S2_MCK	
											TIM15_CH1	
											TIM1_CH2N	
											USART3_RTS	
											I²C2_SDA	
											I²C1_SDA	
36	A7	28	36	31	28	-	PB15	I/O	COM		EVENTOUT	SEG5
											SPI2_MOSI/I²S2_SD	
											TIM15_CH2	
											TIM1_CH3N	
											TIM15_CH1N	
37	A6	-	37	32	-	-	PC6	I/O	COM		TIM3_CH1	SEG4
											SPI2_SCK/I²S2_CK	
											USART4_RX	
											TIM2_CH3	
38	B5	-	38	33	-	-	PC7	I/O	COM		TIM3_CH2	COMP3_INP13,

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											SPI2_MISO/I²S2_MCK	COMP3_INN8 SEG3
											USART4_TX	
											TIM2_CH4	
39	A5	-	39	34	-	-	PC8	I/O	COM		TIM3_CH3	SEG2
											SPI2_MOSI/I²S2_SD	
											USART4_CTS	
											TIM1_CH1	
40	A4	-	40	35	-	-	PC9	I/O	COM		TIM3_CH4	SEG1
											SPI2_NSS/I²S2_WS	
											I²S1_CKIN	
											USART4_RTS	
											TIM1_CH2	
41	A1	29	41	36	29	18	PA8	I/O	COM		EVENTOUT	SEG0, OPA1_OUT
											MCO	
											USART1_CK	
											TIM1_CH1	
											CTC_SYNC	
											SPI2_NSS	
											USART1_TX	
42	A2	30	42	37	30	19	PA9	I/O	COM_F		EVENTOUT	COM0 OPA1_INP
											TIM15_BKIN	
											USART1_TX	
											TIM1_CH2	
											I2C1_SCL	

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											SPI2_MISO	
											MCO	
											I²C2_SCL	
43	B4	31	43	38	31	20	PA10	I/O	COM_F		EVENTOUT	COM1 OPA1_INN
											TIM17_BKIN	
											USART1_RX	
											TIM1_CH3	
											I²C1_SDA	
											SPI2_MOSI	
											I²C2_SDA	
44	A3	32	44	39	32	21	PA11	I/O	COM_U		EVENTOUT	USB_DM COM2
											USART1_CTS	
											TIM1_CH4	
											COMP1_OUT	
											SPI1_MISO/I²S1_MCK	
											TIM1_BKIN2	
45	B3	33	45	40	33	22	PA12	I/O	COM_U		EVENTOUT	USB_DP COM3
											USART1_RTS	
											TIM1_ETR	
											COMP2_OUT	
											SPI1_MOSI/I²S1_SD	
											I²S1_CKIN	
46	B1	34	46	41	34	23	PA13	I/O	COM	(2)	EVENTOUT	-
											SWDIO	

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											IR_OUT	
											USART1_RX	
											COMP3_OUT	
											PVD_OUT	
47	-	35	47	-	35	24	PF5	I/O	COM		TIM1_BKIN2	RTC_OUT
48	-	36	48	-	36	-	PF6	I/O	COM		USART1_CTS	-
49	C4	37	49	42	37	25	PA14	I/O	COM	(2)	EVENTOUT	-
											SWCLK	
											USART2_TX	
											USART1_TX	
											PVD_OUT	
50	D4	38	50	-	38	-	PA15	I/O	COM		EVENTOUT	-
											SPI1_NSS/I²S1_WS	
											USART2_RX	
											TIM2_CH1_ETR	
											USART4_RTS	
											USART3_RTS	
51	E4	-	51	-	-	-	PC10	I/O	COM		USART4_TX	COM4/SEG39
											USART3_TX	
											TIM1_CH3	
52	C2	-	52	-	-	-	PC11	I/O	COM		USART4_RX	COM5/SEG38
											USART3_RX	
											TIM1_CH4	
53	D2	-	53	-	-	-	PC12	I/O	COM		USART4_CK	COM6/SEG37

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											USART3_CK	
											TIM14_CH1	
54	C1	-	54	-	-	-	PF7	I/O	COM		TIM3_ETR	COM7/SEG36
											USART3_RTS	
											TIM1_CH1N	
55	D1	39	55	-	39	-	PB3	I/O	COM		EVENTOUT	COMP2_INN9 SEG35/VLCDH
											SPI1_SCK/I²S1_CK	
											TIM2_CH2	
											USART1_RTS	
											TIM1_CH2	
56	D3	40	56	-	40	26	PB4	I/O	COM		EVENTOUT	COMP1_INP12 COMP2_INP12 SEG34/VLCD3
											SPI1_MISO/I²S1_MCK	
											TIM3_CH1	
											USART1_CTS	
											USART1_CK	
											TIM1_CH2N	
											TIM17_BKIN	
57	E1	41	57	-	41	27	PB5	I/O	COM		SPI1_MOSI/I²S1_SD	COMP1_INP13 SEG33/VLCD2
											TIM3_CH2	
											TIM16_BKIN	
											I²C1_SMBA	
											USART1_CK	
											COMP2_OUT	
											USART1_RTS	

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											USART1_TX	
											TIM1_CH3N	
58	E3	42	58	-	42	28	PB6	I/O	COM_F		EVENTOUT	COMP1_INP14, COMP2_INP14 SEG32/VLCD1
											USART1_TX	
											I^2C1_SCL	
											TIM16_CH1N	
											SPI2_MISO	
											USART3_CTS	
											TIM1_CH3	
											I^2C2_SCL	
59	E2	43	59	-	43	29	PB7	I/O	COM_F		EVENTOUT	PVD_IN, COMP2_INP15 SEG31
											USART1_RX	
											I^2C1_SDA	
											TIM17_CH1N	
											USART4_CTS	
											SPI2_MOSI	
											I^2C2_SDA	
											TIM1_CH1	
60	F1	44	60	-	44	30	PF8/BOOT	I/O	COM	(3)		SEG30
61	G1	45	61	-	45	31	PB8	I/O	COM_F		EVENTOUT	SEG29
											I^2C1_SCL	
											I^2C2_SCL	
											TIM16_CH1	
											SPI2_SCK	

Package							Reset	Ports Type	Ports structure	Notes	Pin functions	
LQFP64 R1	CSP64 R1	LQFP48 C1	QFN64 R1	QFN56 P1	QFN48 C1	QFN32 K1					Alternate functions	Additional functions
											USART1_TX	
											USART3_TX	
											TIM15_BKIN	
											TIM1_CH1N	
62	G2	46	62	-	46	32	PB9	I/O	COM_F		EVENTOUT	SEG28
											IR_OUT	
											I^2C1_SDA	
											TIM17_CH1	
											SPI2_NSS/I^2S2_WS	
											USART1_RX	
											USART3_RX	
											I^2C2_SDA	
63	C7	47	63	-	47	-	V_{SS}	G			Ground	
64	C3	48	64	-	48	-	V_{CC}	S			Digital power supply	
-	F2	-	-	-	-	-	V_{SS}	G			Ground	
-	F3	-	-	-	-	-	V_{CC}	S			Digital power supply	
-	G7	-	-	-	-	-	V_{SS}	G			Ground	
-	F7	-	-	-	-	-	V_{CC}	S			Digital power supply	

1. Configure by option bytes to choose PF2 or NRST.
2. After reset, PA13 and PA14 are configured as SWDIO and SWCLK AF functions, the former has an internal pull-up resistor and the latter has an internal pull-down resistor activated.
3. BOOT0 defaults to digital input mode and pull-down is enable.

3.1. PortA alternate function mapping

Table 3-3 Port A alternate function mapping

PortA	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
PA0	-	USART2_CTS	TIM2_CH1_ETR	-	USART4_TX	-	-	COMP1_OUT	SPI2_SCK	-	-	-	-	-	-	-
PA1	EVENTOUT	USART2_RTS	TIM2_CH2	-	USART4_RX	TIM15_CH1N	I²C1_SMBA	-	SPI1_SCK/ I²S1_CK	SPI2_MOSI	-	-	-	-	-	-
PA2	TIM15_CH1	USART2_TX	TIM2_CH3	-	-	-	-	COM2_OUT	SPI1_MOSI/ I²S1_SD	SPI2_MISO	-	-	-	-	-	-
PA3	TIM15_CH2	USART2_RX	TIM2_CH4	-	-		-	EVENTOUT	SPI2_MSIO	SPI2_NSS/ I²S2_WS	-	-	-	-	-	-
PA4	SPI1_NSS/ I²S1_WS	USART2_CK	-	-	TIM14_CH1	-	-	EVENTOUT	SPI2_MOSI	USART2_TX	-	-	PVD_OUT	-	-	-
PA5	SPI1_SCK/ I²S1_CK	-	TIM2_CH1_ETR	-	-	-	-	EVENTOUT	-	-	USART3_TX	-	-	-	-	-
PA6	SPI1_MISO/ I²S1_MCK	TIM3_CH1	TIM1_BKIN	-	USART3_CTS	TIM16_CH1	EVENTOUT	COMP1_OUT	-	-	-	-	-	-	-	-
PA7	SPI1_MOSI/ I²S1_SD	TIM3_CH2	TIM1_CH1N	-	TIM14_CH1	TIM17_CH1	EVENTOUT	COMP2_OUT	-	-	-	-	-	-	-	-
PA8	MCO	USART1_CK	TIM1_CH1	EVENTOUT	CTC_SYNC	-	-	-	SPI2_NSS	-	USART1_TX	-	-	-	-	-
PA9	TIM15_BKIN	USART1_TX	TIM1_CH2	-	-	-	I²C1_SCL	EVENTOUT	SPI2_MISO	MCO	-	-	-	I²C2_SCL	-	-
PA10	TIM17_BKIN	USART1_RX	TIM1_CH3	-	-	-	I²C1_SDA	EVENTOUT	SPI2_MOSI	-	-	-	-	I²C2SDA	-	-
PA11	EVENTOUT	USART1_CTS	TIM1_CH4	-	-		-	COMP1_OUT	SPI1_MISO/ I²S1_MCK	-	-	TIM1_BKIN2	-	-	-	-
PA12	EVENTOUT	USART1_RTS	TIM1_ETR	-	-	-	-	COMP2_OUT	SPI1_MOSI/ I²S1_SD	I²S1_CKIN	-	-	-	-	-	-
PA13	SWDIO	IROUT	-	-	-	-	-	EVENTOUT	-	USART1_RX	-	COMP3_OUT	PVD_OUT	-	-	-
PA14	SWCLK	USART2_TX	-	-	-	-	-	EVENTOUT	-	USART1_TX	-	-	PVD_OUT	-	-	-
PA15	SPI1_NSS/ I²S1_WS	USART2_RX	TIM2_CH1_ETR	EVENTOUT	USART4_RTS			EVENTOUT			USART3_RTS _DE_CK					

3.2. PortB alternate function mapping

Table 3-4 Port B alternate function mapping

PortB	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
PB0	EVENTOUT	TIM3_CH3	TIM1_CH2N	-	USART3_CK	-	-	COMP1_OUT	SPI1_NSS/ I²S1_WS	-	USART3_RX	-	-	-	-	-
PB1	TIM14_CH1	TIM3_CH4	TIM1_CH3N	-	USART3_RTS	-	-	EVENTOUT	-	-	-	COMP3_OUT	-	-	-	-
PB2	-	-	-	-	-	-	-	EVENTOUT	SPI2_MISO	-	USART3_TX	-	-	-	-	-
PB3	SPI1_SCK/ I²S1_CK	EVENTOUT	TIM2_CH2	-	USART1_RTS	-	-	EVENTOUT	-	-	-	TIM1_CH2	-	-	-	-
PB4	SPI1_MISO/ I²S1_MCK	TIM3_CH1	EVENTOUT	-	USART1_CTS	TIM17_BKIN	-	-	-	-	-	TIM1_CH2N	-	USART1_CK	-	-
PB5	SPI1_MOSI/ I²S1_SD	Tim3_CH2	TIM16_BKIN	I²C1_SMBA	USART1_CK	-	-	COM2_OUT	-	USART1_RTS	-	TIM1_CH3N	-	USART1_TX	-	-
PB6	USART1_TX	I²C1_SCL	TIM16_CH1N	-	-	-	-	EVENTOUT	SPI2_MISO	-	USART3_CTS	TIM1_CH3	-	I²C2_SCL	-	-
PB7	USART1_RX	I²C1_SDA	TIM17_CH1N	-	USART4_CTS	-	-	EVENTOUT	SPI2_MOSI	-	-	TIM1_CH1	-	I²C2_SDA	-	-
PB8	-	I²C1_SCL	TIM16_CH1	-	-	-	-	EVENTOUT	SPI2_SCK	USART1_TX	USART3_TX	TIM15_BKIN	-	I²C2_SCL	TIM1_CH1N	-
PB9	IR_OUT	I²C1_SDA	TIM17_CH1	EVENTOUT	-	SPI2_NSS/ I²S2_WS	-	-	-	USART1_RX	USART3_RX	-	-	I²C2_SDA	-	-
PB10	-	I²C2_SCL	TIM2_CH3	-	USART3_TX	SPI2_SCK/ I²S2_CK	-	COMP1_OUT	-	USART2_RTS	-	-	-	I²C1_SCL	-	-
PB11	EVENTOUT	I²C2_SDA	TIM2_CH4	-	USART3_RX	-	-	COMP2_OUT	SPI2_MOSI	USART2_CTS	-	-	-	I²C1_SDA	-	-
PB12	SPI2_NSS/ I²S2_WS	EVENTOUT	TIM1_BKIN	-	USART3_CK	TIM15_BKIN	-	-	-	-	-	-	-	-	-	-
PB13	SPI2_SCK/ I²S2_CK	-	TIM1_CH1N	-	USART3_CTS	I²C2_SCL	-	EVENTOUT	-	MCO	-	TIM15_CH1N	-	I²C1_SCL	-	-
PB14	SPI2_MISO/ I²S2_MCK	TIM15_CH1	TIM1_CH2N	-	USART3_RTS	I²C2_SDA	-	EVENTOUT	-	-	-	TIM15_CH1	-	I²C1_SDA	-	-
PB15	SPI2_MOSI/ I²S2_SD	TIM15_CH2	TIM1_CH3N	TIM15_CH1N	-	-	-	EVENTOUT	-	-	-	-	-	-	-	-

3.3. PortC alternate function mapping

Table 3-5 Port C alternate function mapping

PortC	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
PC0	EVENTOUT	-	-	-	-	-	-	-	SPI1_MISO/I²S1_MCK	USART2_CTS	USART3_RTS	-	-	-	-	-
PC1	EVENTOUT	-	-	-	-	-	-	-	SPI1_MOSI/I²S1_SD	USART2_RTS	USART3_CTS	TIM15_CH1	-	-	-	-
PC2	EVENTOUT	SPI2_MISO/I²S2_MCK	-	-	-	-	-	-	-	USART3_TX	USART3_RX	TIM15_CH2	-	-	-	-
PC3	EVENTOUT	SPI2_MOSI/I²S2_SD	-	-	-	-	-	-	-	USART3_RX	USART3_TX	-	-	-	-	-
PC4	EVENTOUT	USART3_TX	-	-	-	-	-	COMP3_OUT	SPI1_NSS/I²S1_WS	USART1_TX	-	TIM2_CH1_ETR	IR_OUT	-	-	-
PC5	-	USART3_RX	-	-	-	-	-	-	SPI1_MOSI/I²S1_SD	USART1_RX	-	TM2_CH2	-	-	-	-
PC6	TIM3_CH1	-	-	-	-	-	-	-	SPi2_SCK/I²S2_CK	-	USART4_RXD	TIM2_CH3	-	-	-	-
PC7	TIM3_CH2	-	-	-	-	-	-	-	SPI2_MISO/I²S2_MCK	-	USART4_TX	TIM2_CH4	-	-	-	-
PC8	TIM3_CH3	-	-	-	-	-	-	-	SPI2_MOSI/I²S2_SD	-	USART4_CTS	TIM1_CH1	-	-	-	-
PC9	TIM3_CH4	-	-	-	-	-	-	-	SPI2_NSS/I²S2_WS	I²S1_CKIN	USART4_RTS	TIM1_CH2	-	-	-	-
PC10	USART4_TX	USART3_TX	-	-	-	-	-	-	-	-	-	TIM1_CH3	-	-	-	-
PC11	USART4_RX	USART3_RX	-	-	-	-	-	-	-	-	-	TIM1_CH4	-	-	-	-
PC12	USART4_CK	USART3_CK	-	-	-	-	-	-	-	-	-	TIM14_CH1	-	-	-	-
PC13	-	-	-	-	-	-	-	-	SPI1_SCK/I²S1_CK	-	-	TIM1_BKIN	-	-	-	-
PC14	-	-	-	-	-	-	-	-	-	-	-	TIM1_BKIN2	-	-	-	-
PC15	-	-	-	-	-	-	-	-	-	-	-	TIM15_BKIN	-	-	-	-

3.4. PortF alternate function mapping

Table 3-7 Port F alternate function mapping

PortC	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
PC0	EVENTOUT	-	-	-	-	-	-	-	SPI1_MISO/I2S1_MCK	USART2_CTS	USART3_RTS	-	-	-	-	-
PC1	EVENTOUT	-	-	-	-	-	-	-	SPI1_MOSI/I2S1_SD	USART2_RTS	USART3_CTS	TIM15_CH1	-	-	-	-
PC2	EVENTOUT	SPI2_MISO/I2S2_MCK	-	-	-	-	-	-	-	USART3_TX	USART3_RX	TIM15_CH2	-	-	-	-
PC3	EVENTOUT	SPI2_MOSI/I2S2_SD	-	-	-	-	-	-	-	USART3_RX	USART3_TX	-	-	-	-	-
PC4	EVENTOUT	USART3_TX	-	-	-	-	-	COMP3_OUT	SPI1_NSS/I2S1_WS	USART1_TX	-	TIM2_CH1_ETR	IR_OUT	-	-	-
PC5	-	USART3_RX	-	-	-	-	-	-	SPI1_MOSI/I2S1_SD	USART1_RX	-	TM2_CH2	-	-	-	-
PC6	TIM3_CH1	-	-	-	-	-	-	-	SPi2_SCK/I2S2_CK	-	USART4_RXD	TIM2_CH3	-	-	-	-

PortC	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
PC7	TIM3_CH2	-	-	-	-	-	-	-	SPI2_MISO/I2S2_MCK	-	USART4_TX	TIM2_CH4	-	-	-	-
PC8	TIM3_CH3	-	-	-	-	-	-	-	SPI2_MOSI/I2S2_SD	-	USART4_CTS	TIM1_CH1	-	-	-	-
PC9	TIM3_CH4	-	-	-	-	-	-	-	SPI2_NSS/I2S2_WS	I2S1_CKIN	USART4_RTS	TIM1_CH2	-	-	-	-
PC10	USART4_TX	USART3_TX	-	-	-	-	-	-	-	-	-	TIM1_CH3	-	-	-	-
PC11	USART4_RX	USART3_RX	-	-	-	-	-	-	-	-	-	TIM1_CH4	-	-	-	-
PC12	USART4_CK	USART3_CK	-	-	-	-	-	-	-	-	-	TIM14_CH1	-	-	-	-
PC13	-	-	-	-	-	-	-	-	SPI1_SCK/I2S1_CK	-	-	TIM1_BKIN	-	-	-	-
PC14	-	-	-	-	-	-	-	-	-	-	-	TIM1_BKIN2	-	-	-	-
PC15	-	-	-	-	-	-	-	-	-	-	-	TIM15_BKIN	-	-	-	-

4. Memory Map

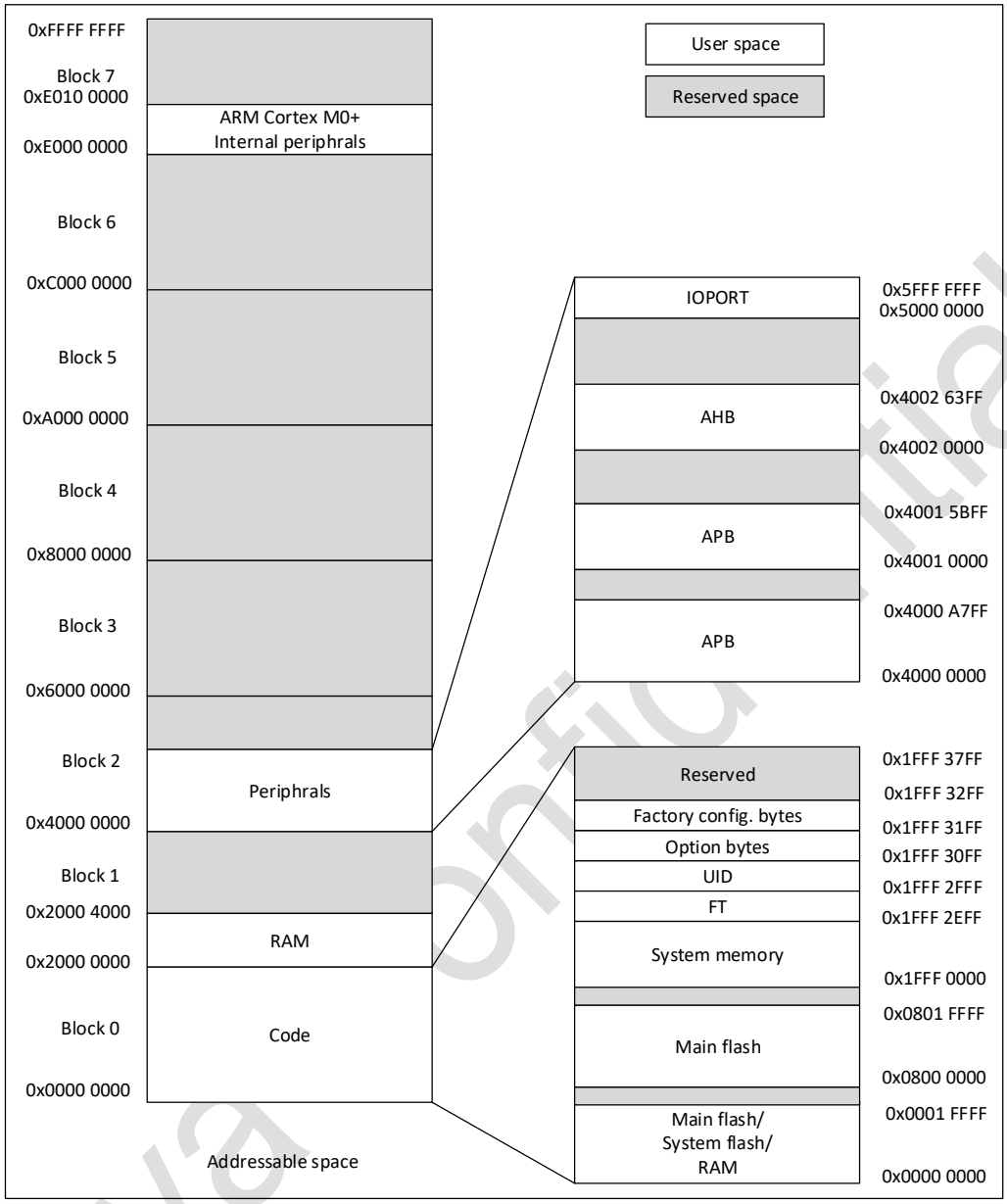


Figure 4-1 Memory map

Table 4-1 Memory boundary address

Type	Boundary Address	Size	Memory Area	Description
SRAM	0x2000 4000-0x3FFF FFFF	-	Reserved	
	0x2000 0000-0x2000 3FFF	16 KBytes	SRAM	If the hardware power-up configuration of the SRAM is 16 KBytes, then the SRAM address space is 0x2000 0000-0x2000 3FFF
Code	0x1FFF 3400-0x1FFF FFFF	-	Reserved	-
	0x1FFF 3300-0x1FFF 33FF	256 Bytes	FT infor1 bytes	Flash Verify Value, Analog 和 Flash Trimming, Debug ID.

Type	Boundary Address	Size	Memory Area	Description
	0x1FFF 3200-0x1FFF 32FF	256 Bytes	FT infor0 bytes	Normal TS DATA, High TS DATA, HSI Re-Trim data, Flash/sram size configuration.
	0x1FFF 3100-0x1FFF 31FF	256 Bytes	Option bytes	option bytes information, IP enable(1)
	0x1FFF 3000-0x1FFF 30FF	256 Bytes	UID bytes	Unique ID
	0x1FFF 0000-0x1FFF 2FFF	12 KBytes	System memory	boot loader
	0x0802 0000-0x1FFE FFFF	-	Reserved	-
	0x0800 0000-0x0801 FFFF	128 KBytes	Main flash memory	-
	0x0002 0000-0x07FF FFFF	-	Reserved	
	0x0000 0000-0x0001 FFFF	128 KBytes	Selected based on Boot configuration, 1）Main flash memory 2）System memory 3）SRAM	

1. Except the above address, other is marked as reserved , which cannot be written , read as 0 , and a response error is generated .

Table 4-2 Peripheral register boundary address

Bus	Boundary Address	Size	Description
	0xE000 000-0xE00F FFFF	1 Mbytes	M0+
IOPORT	0x5000 1800 - 0x5FFF FFFF	256 MB	Reserved
	0x5000 1400 - 0x5000 17FF	1 KB	GPIOF
	0x5000 1000 - 0x5000 13FF	1 KB	Reserved
	0x5000 0C00 - 0x5000 0FFF	1 KB	Reserved
	0x5000 0800 - 0x5000 0BFF	1 KB	GPIOC
	0x5000 0400 - 0x5000 07FF	1 KB	GPIOB
	0x5000 0000 - 0x5000 03FF	1 KB	GPIOA
AHB	0x4002 4000 - 0x4FFF FFFF	256 MB	Reserved
	0x4002 3C00 – 0x4002 3FFF	1 KB	Reserved
	0x4002 3800 –0x4002 3BFF	1 KB	DIV
	0x4002 3400 - 0x4002 37FF	1 KB	Reserved
	0x4002 3000 - 0x4002 33FF	1 KB	CRC
	0x4002 2400 - 0x4002 2FFF	3 KB	Reserved
	0x4002 2000 - 0x4002 23FF	1 KB	FLASH
	0x4002 1C00 - 0x4002 1FFF	1 KB	Reserved
	0x4002 1800 - 0x4002 1BFF	1 KB	EXTI
	0x4002 1400 - 0x4002 17FF	1 KB	Reserved
	0x4002 1000 - 0x4002 13FF	1 KB	RCC(2)
	0x4002 0400 - 0x4002 0FFF	3 KB	Reserved
	0x4002 0000 - 0x4002 03FF	1 KB	DMA

Bus	Boundary Address	Size	Description
APB	0x4001 5C00 - 0x4001 FFFF	41 KB	Reserved
	0x4001 5800 - 0x4001 5BFF	1 KB	DBG
	0x4001 4C00 - 0x4001 57FF	3 KB	Reserved
	0x4001 4800 - 0x4001 4BFF	1 KB	TIM17
	0x4001 4400 - 0x4001 47FF	1 KB	TIM16
	0x4001 4000 - 0x4001 43FF	1 KB	TIM15
	0x4001 3C00 - 0x4001 3FFF	1 KB	Reserved
	0x4001 3800 - 0x4001 3BFF	1 KB	USART1
	0x4001 3400 - 0x4001 37FF	1 KB	Reserved
	0x4001 3000 - 0x4001 33FF	1 KB	SPI1/I2S1
	0x4001 2C00 - 0x4001 2FFF	1 KB	TIM1
	0x4001 2800 - 0x4001 2BFF	1 KB	Reserved
	0x4001 2400 - 0x4001 27FF	1 KB	ADC
	0x4001 0400 - 0x4001 23FF	8 KB	Reserved
	0x4001 0300 - 0x4001 03FF	1 KB	OPA
	0x4001 0200 - 0x4001 02FF		COMP
	0x4001 0000 - 0x4001 01FF		SYSCFG
	0x4000 8000- 0x4000 FFFF	32 KB	Reserved
	0x4000 7C00 - 0x4000 7FFF	1 KB	LPTIM1
	0x4000 7800 - 0x4000 7BFF	-	Reserved
	0x4000 7400 - 0x4000 77FF	-	Reserved
	0x4000 7000 - 0x4000 73FF	1 KB	PWR(3)
	0x4000 6C00 - 0x4000 6FFF	-	Reserved
	0x4000 6800 - 0x4000 6BFF	-	Reserved
	0x4000 6400 - 0x4000 67FF	-	Reserved
	0x4000 6000 - 0x4000 63FF	-	Reserved
	0x4000 5C00 - 0x4000 5FFF	-	Reserved
	0x4000 5800 - 0x4000 5BFF	1 KB	I^2C2
	0x4000 5400 - 0x4000 57FF	1 KB	I^2C1
	0x4000 5000 - 0x4000 53FF	1 KB	Reserved
	0x4000 4C00 - 0x4000 4FFF	1 KB	USART4
	0x4000 4800 - 0x4000 4BFF	1 KB	USART3
	0x4000 4400 - 0x4000 47FF	1 KB	USART2
	0x4000 3C00 - 0x4000 43FF	2 KB	Reserved
	0x4000 3800 - 0x4000 3BFF	1 KB	SPI2/I2S2
	0x4000 3400 - 0x4000 37FF	1 KB	Reserved
	0x4000 3000 - 0x4000 33FF	1 KB	IWDG
	0x4000 2C00 - 0x4000 2FFF	1 KB	WWDG
	0x4000 2800 - 0x4000 2BFF	1 KB	RTC
	0x4000 2400 - 0x4000 27FF	1 KB	LCD

Bus	Boundary Address	Size	Description
	0x4000 2000 - 0x4000 23FF	1 KB	TIM14
	0x4000 1800 - 0x4000 1FFF	2 KB	Reserved
	0x4000 1400 - 0x4000 17FF	1 KB	TIM7
	0x4000 1000 - 0x4000 13FF	1 KB	TIM6
	0x4000 0800 - 0x4000 0FFF	2 KB	Reserved
	0x4000 0400 - 0x4000 07FF	1 KB	TIM3
	0x4000 0000 - 0x4000 03FF	1 KB	TIM2

1. In the above table, the reserved address cannot be written, read back is 0, and a hardfault is generated
2. Not only supports 32 bits word access, but also supports halfword and byte access.
3. Not only supports 32 bits word access, but also supports halfword access.

5. Electrical Characteristics

5.1. Parameter conditions

Unless otherwise specified, all voltages are referenced to V_{SS}.

5.1.1. Minium and maximum values

Unless otherwise specified, the mimimum and maximum values are guaranteed in the worest condotions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at T_A =25°C and T_A =$T_{A(max)}$ (given by the selected temperature range).

Data based on electrical characterization results, design simulations and/or technology charateristics are indicated in the table footnotes and are not tested in production. Based on charaterization, the minimum and maximum values refer to sample tests and represent the mean vaule plus or minus three times the standard deviation.

5.1.2. Typical values

Unless otherwise specified, typical data is based on T_A =25°C and V_{CC} = 3.3V. They are given only as design guidelines and are not tested.

Typical ADC accuracy values are determined by cgaracterization of a batch of samples from a standard diffusion lot over the full temperature range, where 95% of the devices have an error less than equal to the value indicated.

5.2. Absolute maximum ratings

Stresses above the absolute maximum ratings listed in following tables may cause permanent damage to the device. These are stress ratings only and functional opeartion of the device at these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 5-1 Voltage characteristics (1)

Symbol	Ratings	Minimum	Maximum	Unit
V_{CC}	External mains power supply	-0.3	6.25	V
V_{IN}	Input voltage of other pins	-0.3	V_{CC} + 0.3	V

1. Power supply V_{CC} and ground V_{SS} pins must always be connected to the external power supply within the allowable range.

Table 5-2 Current characteristics

Symbol	Describe	Maximum	Unit
I_{VCC}	Flowing into V_{CC} pin (supply current)(1)	300	mA
I_{VSS}	Total current flowing out of V_{SS} pin (outflow current)(1)	300	
$I_{IO(PIN)}$	Output sink current of COM IO(2)	20	
	Source current for all IOs	-20	

1. Power supply V_{CC} and ground V_{SS} pins must always be connected to the external power supply within the allowable range.
2. These I/O types refer to the terms and symbols defined by pins.

Table 5-3 Thermal characteristics

Symbol	Describe	Condition	Value	Unit
T_{STG}	Storage temperature range		-65 to +150	℃
T_O	Range of operating temperature	x 6 version	-40 to +85	℃
		x 7 version	-40 to +105	

5.3. Operating conditions

5.3.1. General operating conditions

Table 5-4 General operating conditions

Symbol	Parameter	Condition	Minimum	Maximum	Unit
f_{HCLK}	Internal AHB clock frequency	-	0	72	MHz
f_{PCLK}	Internal APB Clock frequency	-	0	72	MHz
V_{CC}	Standard operating voltage	-	1.7	5.5	V
V_{CCA}	Operating voltage of analog circuit	Must be the same as V_{CC}	1.7	5.5	V
V_{IN}	I/O input voltage	-	-0.3	V_{CC}+0.3	V
T_A	Ambient temperature	-	-40	85	℃
		-	-40	105	
T_J	Junction temperature	-	-40	90	℃
		-	-40	110	

5.3.2. Operating conditions at power-up / power-down

Table 5-5 Operating conditions at power-up / power-down

Symbol	Parameter	Condition	Minimum	Maximum	Unit
t_{VCC}	V_{CC} rise time rate	-	0	∞	us/V
	V_{CC} fall time rate	-	20	∞	

5.3.3. Embedded reset and LVD module features

Table 5-6 Embedded reset module features

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
V_{PVD}	Programmable voltage detector level selection	PLS[2:0]=000 (Rising edge)	1.7	1.8	1.9	V
		PLS[2:0]=000 (Falling edge)	1.6	1.7	1.8	V
		PLS[2:0]=001 (Rising edge)	1.9	2	2.1	V
		PLS[2:0]=001 (Falling edge)	1.8	1.9	2	V
		PLS[2:0]=010 (Rising edge)	2.1	2.2	2.3	V
		PLS[2:0]=010 (Falling edge)	2	2.1	2.2	V
		PLS[2:0]=011 (Rising edge)	2.3	2.4	2.5	V
		PLS[2:0]=011 (Falling edge)	2.2	2.3	2.4	V
		PLS[2:0]=100 (Rising edge)	2.5	2.6	2.7	V
		PLS[2:0]=100 (Falling edge)	2.4	2.5	2.6	V
		PLS[2:0]=101 (Rising edge)	2.7	2.8	2.9	V
		PLS[2:0]=101 (Falling edge)	2.6	2.7	2.8	V
		PLS[2:0]=110 (Rising edge)	2.9	3	3.1	V

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
		PLS[2:0]=110 (Falling edge)	2.8	2.9	3	V
		PLS[2:0]=111 (Rising edge)	3.1	3.2	3.3	V
		PLS[2:0]=111 (Falling edge)	3	3.1	3.2	V
$V_{PVDhyst}$(1)	PVD hysteresis	-	-	100	-	mV
$V_{POR/PDR}$	Power-on/power-off reset threshold	Rising edge	1.5	1.6	1.7	V
		Falling edge	1.45	1.55	1.65	V
$V_{PDRhyst}$(1)	PDR hysteresis	-	-	20	-	mV
V_{BOR}	BOR Indicates the threshold voltage	BOR_LEV[2:0]=000 (Rising edge)	1.7	1.8	1.9	V
		BOR_LEV[2:0]=000 (Falling edge)	1.6	1.7	1.8	V
		BOR_LEV[2:0]=001 (Rising edge)	1.9	2	2.1	V
		BOR_LEV[2:0]=001 (Falling edge)	1.8	1.9	2	V
		BOR_LEV[2:0]=010 (Rising edge)	2.1	2.2	2.3	V
		BOR_LEV[2:0]=010 (Falling edge)	2	2.1	2.2	V
		BOR_LEV[2:0]=011 (Rising edge)	2.3	2.4	2.5	V
		BOR_LEV[2:0]=011 (Falling edge)	2.2	2.3	2.4	V
		BOR_LEV[2:0]=100 (Rising edge)	2.5	2.6	2.7	V
		BOR_LEV[2:0]=100 (Falling edge)	2.4	2.5	2.6	V
		BOR_LEV[2:0]=101 (Rising edge)	2.7	2.8	2.9	V
		BOR_LEV[2:0]=101 (Falling edge)	2.6	2.7	2.8	V
		BOR_LEV[2:0]=110 (Rising edge)	2.9	3	3.1	V
		BOR_LEV[2:0]=110 (Falling edge)	2.8	2.9	3	V
		BOR_LEV[2:0]=111 (Rising edge)	3.1	3.2	3.3	V
		BOR_LEV[2:0]=111 (Falling edge)	3	3.1	3.2	V
$V_{\_BOR\_hyst}$	BOR hysteresis voltage	-	-	100	-	mV

1. Guaranteed by design, not tested in production.

5.3.4. Operating current characteristics

Table 5-7 Operating mode current

Sym-bol	Condition						Typical (1)	Maximum		Unit
	System clock	Frequency	Code	Run	Peripheral clock	FLASH sleep		T_A= 85 ℃	T_A= 105 ℃	
I_{DD}(run)	PLL	72 MHz	While(1)	Flash	ON	DISABLE	8.37	12.70	-	mA
					OFF	DISABLE	4.60	7.80	-	
		48 MHz			ON	DISABLE	6.54	9.73	-	
					OFF	DISABLE	4.01	6.46	-	
	HSI	24 MHz			ON	DISABLE	3.82	6.57	-	
					OFF	DISABLE	2.60	5.07	-	
		16 MHz			ON	DISABLE	2.78	4.94	-	
					OFF	DISABLE	1.90	2.75	-	
		8 MHz			ON	DISABLE	1.80	3.40	-	
					OFF	DISABLE	1.21	2.73	-	
		4 MHz			ON	DISABLE	1.04	2.22	-	
					OFF	DISABLE	0.87	1.34	-	
	LSI	32.768 kHz			ON	DISABLE	350.2	824.5	-	uA
					OFF	DISABLE	293.2	770.5	-	
		32.768 kHz			ON	ENABLE	276.7	720.6	-	
					OFF	ENABLE	224.6	663.2	-	

1. Data is based on assessment results and is not tested in production.

Table 5-8 Sleep mode current

Symbol	Condition				Typical (1)	Maximum		Unit
	System clock	Frequency	Peripheral clock	FLASH sleep		T_A= 85 ℃	T_A= 105 ℃	
I_{DD} (sleep)	PLL	72MHz	ON	DISABLE	6.16	8.36	-	mA
			OFF	DISABLE	2.13	3.14	-	
	HSI	48MHz	ON	DISABLE	4.57	6.34	-	
			OFF	DISABLE	1.82	2.73	-	
		24MHz	ON	DISABLE	2.12	3.21	-	
			OFF	DISABLE	0.89	1.54	-	
		16MHz	ON	DISABLE	1.56	2.75	-	
			OFF	DISABLE	0.71	1.53	-	
		8MHz	ON	DISABLE	1.01	1.73	-	
			OFF	DISABLE	0.53	1.01	-	
		4MHz	ON	DISABLE	0.74	1.40	-	
			OFF	DISABLE	0.46	0.91	-	
	LSI	32.768kHz	ON	DISABLE	349.4	824.5	-	uA
			OFF	DISABLE	292.5	770.5	-	
		32.768kHz	ON	ENABLE	278.4	720.6	-	
			OFF	ENABLE	224.4	663.2	-	

1. Data is based on assessment results and is not tested in production.

Table 5-9 Stop mode current

Sym-bol	Condition					Typical (1)	Maximum		unit
	V_{CC}	V_{DD}	MR/LPR	LSI	Peripheral clock		T_A= 85 ℃	T_A= 105 ℃	
I_{DD} (stop)	1.7 to 5.5V	1.2V	MR	-	-	130.30	245.43	-	uA
		1.2V	LPR	ON	RTC+IWDG+LPTIM	6.60	104.01	-	
					IWDG	6.70	103.83	-	
					LPTIM	6.70	103.62	-	
					RTC	6.60	103.63	-	
				OFF	No	6.50	104.26	-	
		1.0V		ON	RTC+IWDG+LPTIM	5.80	81.71	-	
					IWDG	5.80	81.51	-	
					LPTIM	5.70	81.37	-	
					RTC	5.70	81.55	-	
				OFF	No	5.50	81.39	-	

1. Data is based on assessment results and is not tested in production.

5.3.5. Wake-up time for low power mode

Table 5-10 Low power mode wake-up time

Symbol	Parameters(1)		Condition	Typical (2)	Maximum	Unit
$t_{WUSLEEP}$	Wake-up from sleep mode		-	7	-	CPU Cycles
t_{WUSTOP}		Powered by MR	Execute program in Flash, HSI (24 MHz) as system clock	3.5	-	us

Symbol	Parameters(1)		Condition		Typical (2)	Maximum	Unit
	Wake-up from stop mode	Powered by LPR	Execute program in Flash, HSI as system clock	V_{DD}=1.2V	7	-	
				V_{DD}=1.0V	7	-	

1. The wake-up time is measured from the wake-up time until the first instruction is read by the user program.
2. Data is based on assessment results and is not tested in production.

5.3.6. External clock source characteristics

5.3.6.1. External high-speed clock

In bypass mode of HSE (the HSEBYP of RCC_CR is set), when the high-speed start-up circuit in the chip stops working, the corresponding I/O is used as a standard GPIO.

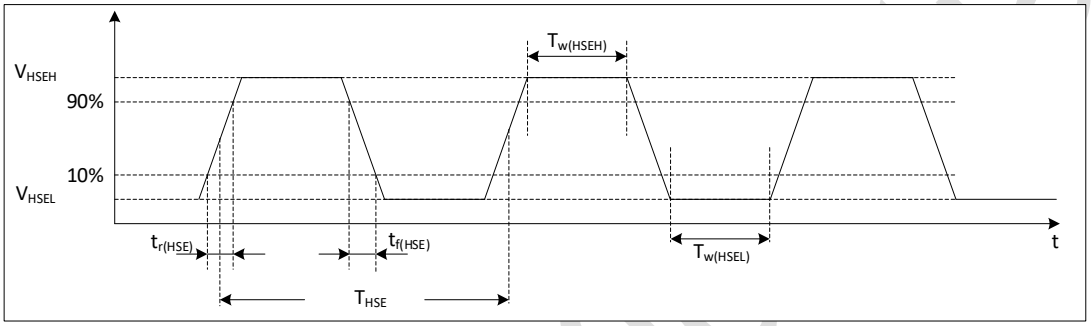


Figure 5-1 External high-speed clock timing diagram

Table 5-11 External high-speed clock features

Symbol	Parameters(1)	Minimum	Typical	Maximum	Unit
f_{HSE_ext}	User external clock source frequency	0	8	32	MHz
V_{HSEH}	Input pin high level voltage	0.7V_{CC}	-	V_{CC}	V
V_{HSEL}	Input pin low level voltage	V_{SS}	-	0.3V_{CC}	
$t_{W(HSEH)}$ $t_{W(HSEL)}$	Enter high or low time	15	-	-	ns
$t_{r(HSE)}$ $t_{f(HSE)}$	Enter the rise/fall time	-	-	20	ns

1. Guaranteed by design, not tested in production.

5.3.6.2. External low-speed clock

In the bypass mode of LSE (the LSE BYP of RCC_BDCR is set), the low-speed start-up circuit in the chip stops working, and the corresponding I/O is used as a standard GPIO.

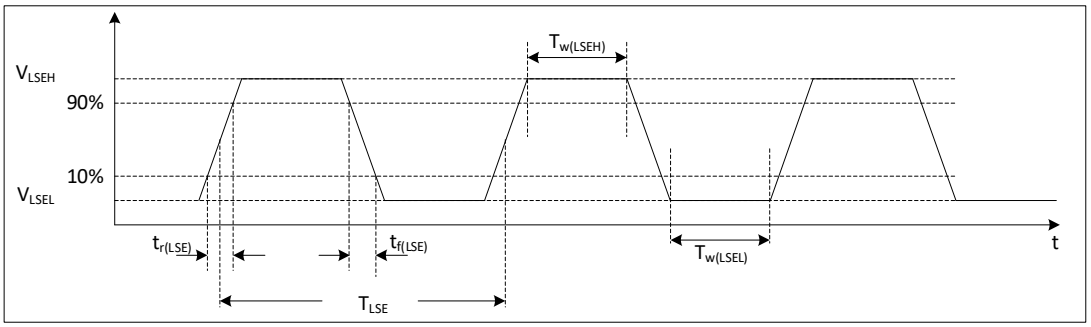


Figure 5-2 External low-speed clock timing diagram

Table 5-12 External low-speed clock characteristics

Symbol	Parameters(1)	Minimum	Typical	Maximum	Unit
f_{LSE_ext}	User external clock frequency	-	32.768	1000	KHz
V_{LSEH}	Input pin high level voltage	$0.7V_{CC}$	-	-	V
V_{LSEL}	Input pin low level voltage	-	-	$0.3V_{CC}$	V
$t_{W(LSEH)}$ $t_{W(LSEL)}$	Enter high or low time	450	-	-	ns
$t_{r(LSE)}$ $t_{f(LSE)}$	Enter the rise/fall time	-	-	50	ns

1. Guaranteed by design, not tested in production .

5.3.6.3. External high-speed crystal

The high-speed external (HSE) clock can be supplied with a ~32 MHz crystal/ceramic resonator oscillator. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time.

Table 5-13 External high-speed crystal characteristics

Symbol	Parameter	Condition(1)	Minimum (2)	Typical	Maximum (2)	Unit
f_{OSC_IN}	Oscillation frequency	-	1	-	32	MHz
I_{DD}(4)	HSE current consumption	During startup	-	-	5.5	mA
		V_{CC} = 3 V, Rm = 30 Ω, C_L = 10 pF@8 MHz	-	0.58	-	
		V_{CC} = 3 V, Rm = 45 Ω, C_L = 10 pF@8 MHz	-	0.59	-	
		V_{CC} = 3 V, Rm = 30 Ω, C_L = 5 pF@48 MHz	-	0.89	-	
		V_{CC} = 3 V, Rm = 30 Ω, CL = 10 pF@48 MHz	-	1.14	-	
		V_{CC} = 3 V, Rm = 30 Ω, C_L = 20 pF@48 MHz	-	1.94	-	
$t_{SU(HSE)}$(3)(4)	Startup Time	f_{OSC_IN} = 32 MHz	-	2	-	ms
		f_{OSC_IN} = 4 MHz	-	2	-	

1. Crystal/ceramic resonator characteristics are based on the manufacturer's datasheet.
2. Guaranteed by design, not tested in production.

3. $t_{SU(HSE)}$ is the startup time from enable (by software) to when the clock oscillation reaches a stable state , measured for a standard crystal/resonator, which can vary considerably from one crystal/resonator to another .
4. Data is based on assessment results and is not tested in production.

5.3.6.4. External low speed crystal

The low-speed external (LSE) clock can be supplied with a 32.768 KHz crystal resonator oscillator. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time.

Table 5-14 External low-speed crystal feature

Symbol	Parameter	Condition(1)	Minimum (2)	Typical	Maximum (2)	Unit
I_{DD}(4)	LSE current consumption	LSE_DRIVER [1:0] = 00	-	250	-	nA
		LSE_DRIVER [1:0] = 01	-	560	-	
		LSE_DRIVER [1:0] = 10	-	920	-	
		LSE_DRIVER[1:0] = 11	-	1260	-	
$t_{SU(LSE)}$(3)(4)	Startup Time	-	-	3	-	s

1. Crystal/ceramic resonator characteristics are based on the manufacturer's datasheet.
2. Guaranteed by design, not tested in production.
3. $t_{SU(LSE)}$ is the startup time from enable (by software) to when the clock oscillation reaches a stable , measured for a standard crystal/resonator , which may vary greatly from crystal to resonator.
4. Data is based on assessment results and is not tested in production.

5.3.7. Internal high frequency clock source HSI characteristics

Table 5-15 Internal high frequency clock source characteristics

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
f_{HSI}	HSI frequency	-	-	4.0 8.0 16.0 22.12 24.0	-	MHz
$\Delta T_{emp\ (HSI)}$	HSI frequency temperature drift	V_{CC} = 1.7 to 5.5 V, T_A = 25 °C	-1(2)	-	1(2)	%
		V_{CC} = 1.7 to 5.5 V, T_A = 0 to 85 °C	-2(2)	-	2(2)	
		V_{CC} = 1.7 to 5.5 V, T_A = -40 to 85 °C	-4(2)	-	2(2)	
		V_{CC} = 1.7 to 5.5 V, T_A = -40 to 105 °C	-4(2)	-	4(2)	
f_{TRIM} (1)	HSI fine-tuning accuracy	-	-	0.1	-	%
$\Delta T_{emp(HSI)}$	HSI frequency temperature drift	-	45(1)	-	55(1)	%

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
$t_{Stab\ (HSI)}$	HSI stabilization time	-	-	2	4(1)	us
f_{TRIM}(1)	HSI fine-tuning accuracy	4 MHz	-	110	-	uA
		8 MHz	-	120	-	
		16 MHz	-	170	-	
		22.12 MHz, 24 MHz	-	210	-	

1. Guaranteed by design, not tested in production.
2. Data is based on assessment results and is not tested in production.

5.3.8. Internal low frequency clock source LSI characteristics

Table 5-17 Internal low frequency clock characteristics

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
f_{LSI}	LSI frequency	-	-	32.768	-	KHz
$\Delta T_{emp(LSI)}$	LSI frequency temperature drift	V_{CC} = 3.3 V, T_A = 25 °C	-3	-	+3	%
		V_{CC} = 1.7 ~ 5.5 V, T_A = 0 to 85 °C	-10(2)	-	10(2)	
		V_{CC}=1.7 ~ 5.5 V, T_A= 0 ~105 °C	- 15(2)	-	15(2)	
		V_{CC} = 1.7 ~ 5.5 V, T_A = -40 to 105 °C	-20(2)	-	20(2)	
f_{TRIM}(1)	LSI fine-tuning accuracy	-	-	0.2	-	%
$t_{Stab(LSI)}$(1)	LSI stabilization time	-	-	150	-	us
$I_{DD(LSI)}$(1)	LSI current consumption	-	-	300	-	nA

1. Guaranteed by design, not tested in production.
2. Data is based on assessment results and is not tested in production.

5.3.9. Phase locked loop (PLL) characteristics

Table 5-16 Phase locked loop characteristics

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
f_{PLL_IN}	input frequency	T_A = 25 °C, V_{CC} = 3.3 V PLL *2	16(1)	-	24(1)	MHz
		T_A = 25 °C, V_{CC} = 3.3 V PLL *3	22.12(1)	-	24(1)	
f_{PLL_OUT}	Output frequency	T_A = 25 °C, V_{CC} = 3.3 V	32(1)	-	72	MHz
Jitter	Period jitter	-	-	-	0.3(1)	ns
t_{LOCK}	Latch time	f_{PLL_IN} = 24 MHz	-	15	40(1)	us

1. Guaranteed by design, not tested in production.

5.3.10. Memory characteristics

Table 5-17 Memory characteristics

Symbol	Parameter	Condition	Typical	Maximum (1)	Unit
t_{prog}	Page program	-	1.0	1.5	ms
t_{ERASE}	Page/sector/mass erase	-	3.0	4.5	ms
I_{DD}	Page programe	-	2.1	2.9	mA

Symbol	Parameter	Condition	Typical	Maximum (1)	Unit
	Page/sector/mass erase	-	2.1	2.9	mA

1. Guaranteed by design, not tested in production.

Table 5-18 Memory erase times and data retention

Symbol	Parameter	Condition	Minimum(1)	Unit
N_{END}	Erase and write times	T_A = - 40 ~ 85 ℃	100	kcycle
		T_A = 85 ~ 105 ℃	10	
t_{RET}	Data retention period	10 Kcycle T_A = 55 ℃	20	Year

1. Data is based on assessment results and is not tested in production.

5.3.11. EFT characteristics

Symbol	Parameter	Condition	Grade	Typical	Unit
EFT to IO	-	IEC61000-4-4	B	2	kV
EFT to Power	-	IEC61000-4-4	B	4	kV

5.3.12. ESD & LU characteristics

Table 5-19ESD & LU characteristics

Symbol	Parameter	Condition	Typical	Unit
$V_{ESD(HBM)}$	Static discharge voltage (human body model)	ESDA/JEDEC JS-001-2017	7.5	KV
$V_{ESD(CDM)}$	Static discharge voltage (charging equip-ment model)	ESDA/JEDEC JS-002-2018	1	KV
$V_{ESD(MM)}$	Static discharge voltage (machine model)	JESD22-A115C	200	V
LU	Static latch-up	JESD78E	200	mA

5.3.13. Port characteristics

Table 5-20 IO static characteristics

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
V_{IH}	Input high level voltage	V_{CC} = 1.7 to 5.5 V	0.7V_{CC}	-	-	V
V_{IL}	Input low level voltage	V_{CC} = 1.7 to 5.5 V	-	-	0.3V_{CC}	V
V_{hys}(1)	Schmitt hysteresis voltage	-	-	200		mV
I_{lkg}	Input leakage current	-	-	-	1	uA
R_{PU}	Pull-up resistor	-	30	50	70	kΩ
R_{PD}	Pull-down resistor	-	30	50	70	kΩ
C_{IO}(1)	Pin capacitance	-	-	5	-	pF

1. Guaranteed by design, not tested in production.

Table 5-21 Output voltage characteristics

Symbol	Parameters(1)	Condition	Minimum	Maximum	Unit
V_{OL}	COM IO output low level	I_{OL} = 8 mA, V_{CC} ≥ 2.7 V	-	0.4	V
V_{OL}		I_{OL} = 4 mA, V_{CC} = 1.8 V	-	0.5	V
V_{OL}(3)		I_{OL} = 8 mA, V_{CC} ≥ 2.7 V	-	0.4	V

V_{OL}(3)	Output low level voltage for an I/O pin	I_{OL} = 4 mA, V_{CC} = 1.8 V	-	0.4	V
V_{OH}	COM IO output high level	I_{OH} = 8 mA, V_{CC} ≥ 2.7 V	V_{CC}–0.4	-	V
V_{OH}		I_{OH} = 4 mA, V_{CC} = 1.8 V	V_{CC}–0.5	-	V
V_{OH}(3)	Output high level voltage for an I/O pin	I_{OL} = 8 mA, V_{CC} ≥ 2.7 V	V_{CC}–0.4		V
V_{OH}(3)		I_{OL} = 4 mA, V_{CC} = 1.8 V	V_{CC}–0.4		V

1. IO types can refer to the terms and symbols defined by the pins.
2. Data is based on assessment results and is not tested in production.

5.3.14. NRST pin characteristics

Table 5-22 NRST pin characteristics

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
V_{IH}	Input high level voltage	V_{CC} = 1.7 to 5.5 V	0.7V_{CC}	-	-	V
V_{IL}	Input low level voltage	V_{CC} = 1.7 to 5.5 V	-	-	0.2V_{CC}	V
V_{hys}(1)	Schmitt hysteresis voltage	-	-	300	-	mV
I_{lkg}	Input leakage current	-	-	-	1	uA
RPU(1)	Pull-up resistor	-	30	50	70	kΩ
RPD(1)	Pull-down resistor	-	30	50	70	kΩ
C_{IO} _	Pin capacitance	-	-	5	-	pF

1. Guaranteed by design, not tested in production.

5.3.15. ADC characteristics

Table 5-23 ADC characteristics

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
I_{CC}	Current consumption	@0.75MSPS	-	0.4	-	mA
C_{IN}(1)	Internal sample and hold capacitors	-	-	5	8	pF
F_{ADC}	Convert clock frequency	V_{CC} = 1.7 to 2.3 V	1	4	8(2)	MHz
		V_{CC} = 2.3 to 5.5 V	1	8	16(2)	MHz
t_{samp}(1)	-	V_{CC} = 1.7 to 2.3 V	3.5* Tclk		41.5* Tclk	
t_{conv}(1)	-	-	-	12*Tclk	-	
t_{eoc}(1)	-	-	-	0.5*Tclk	-	
DNL(2)	RT	-	-	±1	-1~1.5	LSB
INL(2)	RT	-	-		±3	LSB
Offset(2)	RT	-		±1.5	±3	LSB

1. Guaranteed by design, not tested in production.
2. Data is based on assessment results and is not tested in production.

5.3.16. DAC characteristics

Table 5-24 DAC characteristics

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Comments
V_{DDA}	Analog supply voltage	2.2	-	5.5	V	-
R_{LOAD}(1)	Resistive load vs. V_{SSA} with buffer ON	5	-	-	kΩ	

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Comments
	Resistive load vs. V_{CCA} with buffer ON	15	-	-	kΩ	
R_O(1)	Impedance output with buffer OFF	-	-	15	kΩ	The minimum resistive load between DAC_VOUT and V_{SS} to have a 1% accuracy is 1.5 MΩ .
C_{LOAD}(1)	Capacitive load	-	-	50	pF	Maximum capacitive load at DAC_OUT pin (when the buffer is ON).
DAC_OUT min(1)	Lower DAC_OUT voltage with buffer ON	0.2	-	-	V	It gives the maximum output excursion of the DAC.
DAC_OUT max(1)	Higher DAC_OUT voltage with buffer ON	-	-	V_{DDA} - 0.2	V	
DAC_OUT min(1)	Lower DAC_OUT voltage with buffer OFF	-	0.5	-	mV	It gives the maximum output excursion of the DAC.
DAC_OUT max(1)	Higher DAC_OUT voltage with buffer OFF	-	-	V_{DDA} – 10 mV	V	
I_{DDA}(1)	DAC DC current consumption in quiescentmode (2)	-	-	600	μA	With no load, middle code (0x800) on the inputs
		-	-	700	μA	With no load, worst code (0xF1C) at V_{REF}+ = 3.6 V in terms of DC consumption on the inputs
DNL(2)	Differential linearity error	-	-	±1	LSB	Given for the DAC in 10 bits configuration
		-	-	±3	LSB	Given for the DAC in 12 bits configuration
INL(2)	Integral linearity error	-	-	±1	LSB	Given for the DAC in 10 bits configuration
				±4	LSB	Given for the DAC in 12 bits configuration
Offset(2)	offset error	-	-	±3	LSB	Given for the DAC in 10 bits
		-	-	±12	LSB	Given for the DAC in 12 bits
Gain error(2)	Gain error	-	-	±0.5	%	Given for the DAC in 12 bits configuration
$t_{SETTLING}$(2)	Settling time (full scale: for a 10 bits input code transition between the lowest and the highest input codes when	-	4	10	μs	C_{LOAD} ≤ 50 pF, R_{LOAD} ≥ 5 kΩ

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Comments
	DAC_OUT reaches finalvalue ±1LSB					
Update rate(2)	Max frequency for a correct DAC_OUT change when small variation in the inputcode (from code i to i+1LSB)	-	-	1	MS/s	C_{LOAD} ≤ 50 pF, R_{LOAD} ≥ 5 kΩ
t_{WAKEUP}(2)	Wakeup time from off state	-	6.5	10	µs	C_{LOAD} ≤ 50 pF, R_{LOAD} ≥ 5 kΩ input code between lowest and highest possible ones.
P_{SRR+}(1)	Power supply rejection ratio (to V_{DDA}) (static DC measurement	-	-67	-40	dB	No R_{LOAD} , C_{LOAD} = 50 pF

5.3.17. Comparator characteristics

Table 5-25 Comparator characteristics(1)

Symbol	Parameter	Condition		Minimum	Typical	Maximum	Unit
V_{IN}	Input voltage range			0		V_{CC}	V
V_{SC}	Scaler offset voltage				±5	± 10	mV
$I_{DD(SCALER)}$	Scaler static consumption				0.8	1	uA
t_{START_SCALER}	Scaler startup time				100	200	us
t_{START}	Startup time to reach propagation delay specification	High-speed mode				5	us
		Medium-speed mode				15	
t_D	Propagation delay	200 mV step, 100 mV overdrive	High-speed mode		40	70	ns
			Medium-speed mode		0.9	2.3	us
		>200 mV step, 100 mV overdrive	High-speed mode			85	ns
			Medium-speed mode			3.4	us
V_{offset}	Offset error				±5		mV
V_{hys}	Hysteresis	No hysteresis			0		mV
		With hysteresis			20		
I_{DD}	Consumption	Medium-speed mode, no deglitcher	Static		5		uA
			With 50 KHz and ±100 mv overdrive square signal		6		uA

Symbol	Parameter	Condition		Minimum	Typical	Maximum	Unit
		Medium-speed mode, with de-glitcher	Static		7		uA
			With 50 KHz and ±100 mv overdrive square signal		8		uA
		High-speed mode, no deglitcher	Static		250		uA
			With 50 KHz and ±100 mv overdrive square signal		250		uA

1. Guaranteed by design, not tested in production.

5.3.18. Operational amplifier characteristics

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
V_i	Input voltage	-	0	-	AV_{CC}	V
V_o	The output voltage	-	0.1	-	AV_{CC} - 0.2	V
I_o	Output current	-	-	-	2.2	mA
R_L	load time	-	5K	-	-	Ω
t_{start}	Initialization time	-	-	-	20	us
V_{io}	Input offset voltage	-	--	±6	-	mV
PM	Phase margin	-	-	80	-	Deg
UGBW	Unity gain width	-	-	10	-	MHz
SR	Slew rate	-	-	8	-	V/us

5.3.19. Temperature sensor characteristics

Table 5-26 Temperature sensor characteristics

Symbol	Parameter	Minimum	Typical	Maximum	Unit
T_L(1)	V_{TS} linearity with temperature	-	±1	±2	℃
Avg_Slope(1)	Average slope	2.3	2.5	2.7	mV/℃
V_{30}	Voltage at 30 ℃ (±5 ℃)	0.742	0.76	0.785	V
t_{START}(1)	Start up time entering in continuous mode	-	70	120	us
t_{s_temp}(1)	ADC sampling time when reading the temperature	9	-	-	us

1. Guaranteed by design, not tested in production.
2. Data is based on assessment results and is not tested in production.

5.3.20. Built-in reference voltage characteristics

Table 5-27 Built-in reference voltage characteristics

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Unit
V_{REFINT}	Internal reference voltage	-	1.17	1.2	1.23	V
$t_{start\_vrefint}$	Start time of internal reference voltage	-	-	10	15	us
T_{coeff}	Temperature coefficient	-	-	-	100(1)	ppm/°C
I_{vcc}	Current consumption from V_{CC}	-	-	12	20	uA
T_{coeff}	Internal 2.5V/1.5V temperature coefficient	T_A=-40 ~ 105 °C	-	-	120	ppm/°C

1. Guaranteed by design, not tested in production.

5.3.21. Timer characteristics

Table 5-28 Timer characteristics

Symbol	Parameter	Condition	Minimum	Maximum	Unit
$t_{res(TIM)}$	Timer resolution time	-	1	-	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 72 MHz	13.889	-	ns
f_{EXT}	Timer external clock frequency on CH1 to CH4	-	-	$f_{TIMxCLK}/2$	MHz
		$f_{TIMxCLK}$ = 72 MHz	-	24	
Res_{TIM}	Timer resolution	TIM1/3/14/15/16/17	-	16	Bit
$t_{COUNTER}$	16 bits counter clock period	-	1	65536	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 72 MHz	0.013889	913	us

Table 5-29LPTIM characteristics (clock selection LSI)

Prescaler	PRESC [2:0]	Minimum overflow value	Maximum overflow value	Unit
/1	0	0.0305	1998.848	ms
/2	1	0.0610	3997.696	
/4	2	0.1221	8001.9456	
/8	3	0.2441	15997.3376	
/16	4	0.4883	32001.2288	
/32	5	0.9766	64002.4576	
/64	6	1.9531	127998.3616	
/128	7	3.9063	256003.2768	

Table 5-30IWDG characteristics (clock selection LSI)

Prescaler	PR[2:0]	Minimum overflow value	Maximum overflow value	Unit
/4	0	0.122	499.712	ms
/8	1	0.244	999.424	
/16	2	0.488	1998.848	
/32	3	0.976	3997.696	
/64	4	1.952	7995.392	
/128	5	3.904	15990.784	
/256	6 or 7	7.808	31981.568	

Table 5-31 WWDG characteristics (Clock selection 4 8MHz PCLK)

Prescaler	WDGTB[1:0]	Minimum overflow value	Maximum overflow value	Unit
1*4096	0	0.085	5.461	ms
2*4096	1	0.171	10.923	
4*4096	2	0.341	21.845	
8*4096	3	0.683	43.691	

5.3.22. Communication port characteristics

5.3.22.1. I²C bus interface features

The I²C interface meets the timing requirements of the I²C-bus specification and user manual:

- Standard-mode (Sm): 100 kbit/s
- Fast-mode (Fm): 400 kbit/s

The I²C timings requirements is guaranteed by design, provided the I²C peripheral is properly configured and the I²C CLK frequency is greater than the minimum required in the table below.

Table 5-32 Minimum I²C CLK frequency

Symbol	Parameter	Condition	Minimum	Unit
$f_{I2CCLK(min)}$	Minimum I²C CLK frequency	Standard-mode	2	MHz
		Fast-mode	9	

I²C SDA and SCL pins have analogue filtering, see table below.

Table 5-33 I²C filter characteristics

Symbol	Parameter	Minimum	Maximum	Unit
t_{AF}	Lmiting duration of spikes suppressed by the filter (spikers shorter than the limiting duration are suppressed)	50	260	ns

5.3.22.2. Serial peripheral interface (SPI) characteristics

Table 5-34 SPI characteristics

Symbol	Parameter	Condition	Minimum	Maximum	Unit
f_{SCK} $1/t_{c(SCK)}$	SPI clock frequency	Master mode	-	12	MHz
		Slave mode	-	12	
$t_{r(SCK)}$ $t_{f(SCK)}$	SPI clock rise and fall time	Capacitive load: C = 15 pF	-	6	ns
$t_{su(NSS)}$	NSS setup time	Slave mode	4Tpclk	-	ns
$t_{h(NSS)}$	NSS hold time	Slave mode	2Tpclk + 10	-	ns
$t_{w(SCKH)}$ $t_{w(SCKL)}$	SCK high and low time	Master mode, f_{PCLK} = 36 MHz, presc = 4	Tpclk*2 - 2	Tpclk*2 + 1	ns
$t_{su(MI)}$ $t_{su(SI)}$	Data input setup time	Master mode, presc = 4	Tpclk + 5(1)	-	ns
		Slave mode, presc = 4	5	-	
$t_{h(MI)}$	Data input hold time	Master mode	5	-	ns
$t_{h(SI)}$		Slave mode	Tpclk + 5	-	
$t_{a(SO)}$	Data output access time	Slave mode, presc = 4	0	3Tpclk	ns

Symbol	Parameter	Condition	Minimum	Maximum	Unit
$t_{dis(SO)}$	Data output disable time	Slave mode	2Tpclk + 5	4Tpclk + 5	ns
$t_{v(SO)}$	Data output valid time	Slave mode (after enable edge), presc = 4	0	1.5Tpclk(2)	ns
$t_{v(MO)}$	Data output valid time	Master mode (after enable edge)	-	6	ns
$t_{h(SO)}$	Data output hold time	Slave mode, presc = 4	0(3)	-	ns
$t_{h(MO)}$		Master mode	2	-	
DuCy(SCK)	SPI slave input clock duty cycle	Slave mode	45	55	%

1. The Master generates a 1 pclk receive control signal before the receive edge.
2. Slave has a maximum of 1 pclk based on the sending edge of SCK delay, considering IO delay, etc., define 1.5 pclk.
3. Between the receiving edge and the sending edge , the slave updates the data before the sending edge.

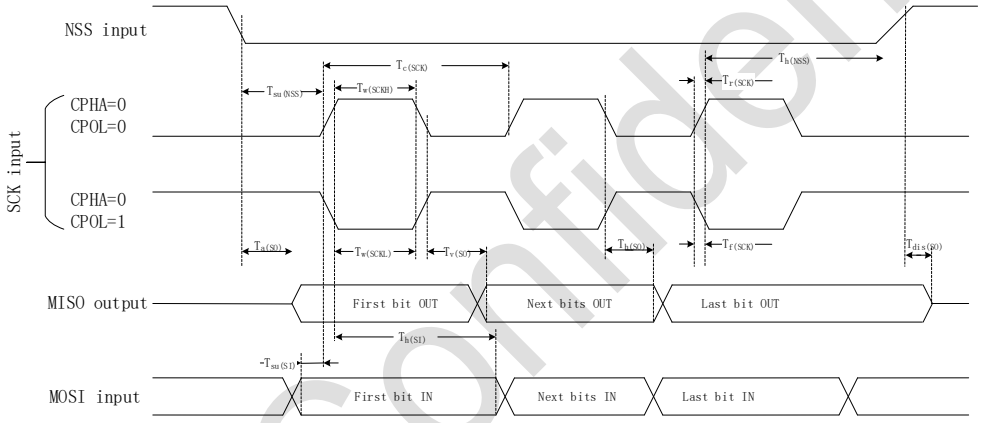


Figure 5-3 SPI timing diagram – slave mode and CPHA=0

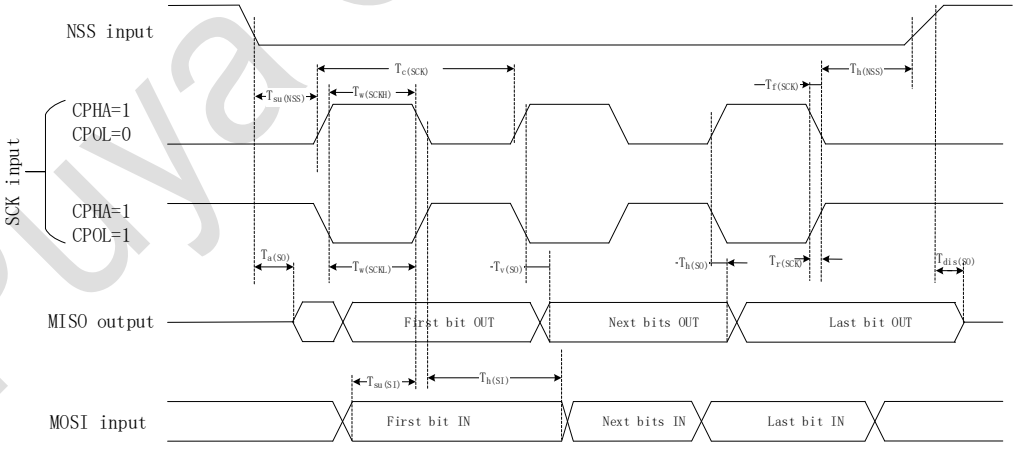


Figure 5-4 SPI timing diagram – slave mode and CPHA=1

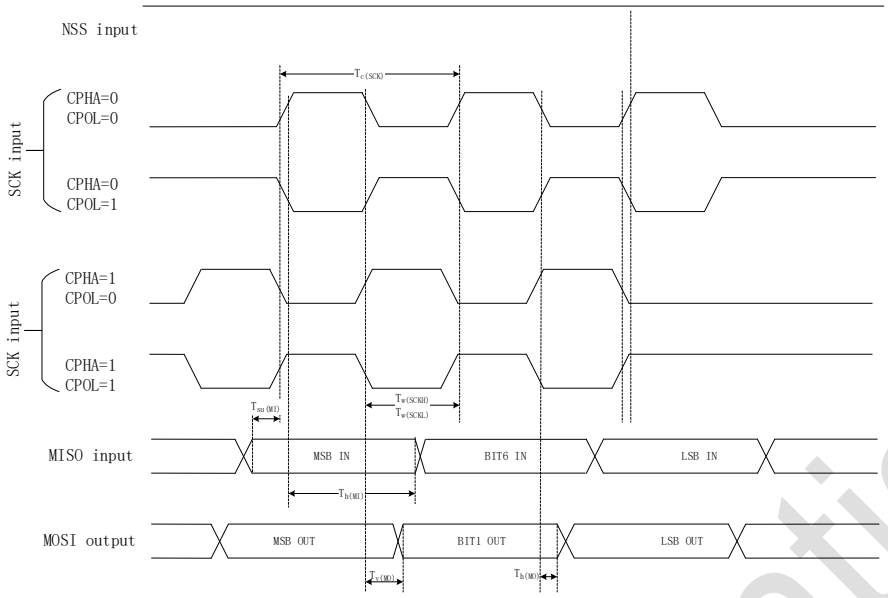
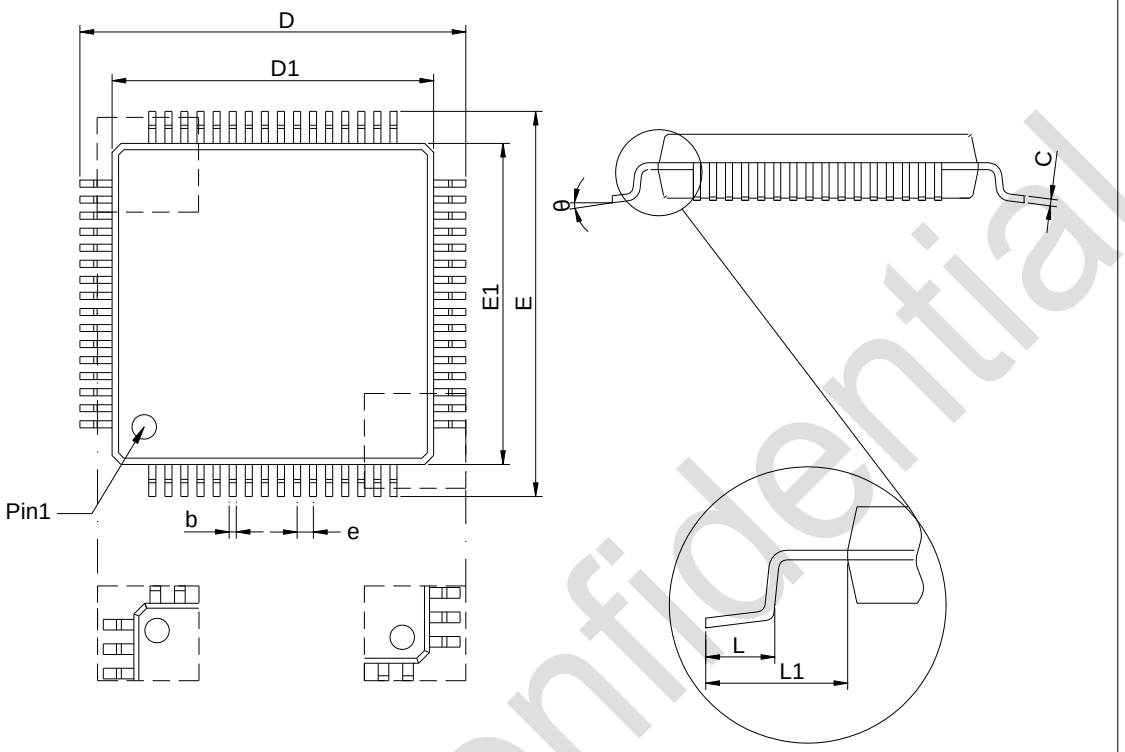
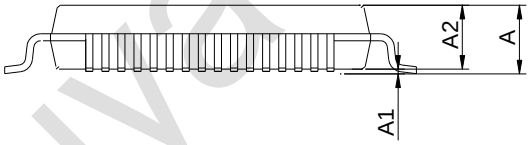


Figure 5-5 SPI timing diagram – master mode

6. Package Information

6.1. LQFP64





Common Dimensions

(Unit of Measure=millimeters)

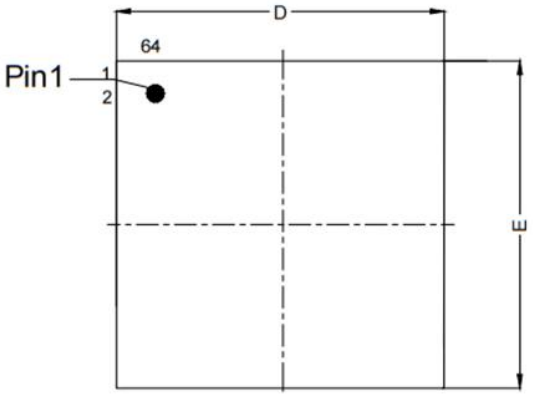
Symbol	Min	Typ	Max
A	-	-	1.600
A1	0.050	-	0.150
A2	1.350	1.400	1.450
b	0.180	-	0.270
c	0.130	-	0.180
D	11.950	12.000	12.050
D1	9.900	10.000	10.100
E	11.950	12.000	12.050
E1	9.900	10.000	10.100
e		0.500BSC	
L	0.530	-	0.700
L1		1.000REF	
θ	0	-	7°

Note：1. Dimensions are not to scale
2.Have two shape can be compatible with each other

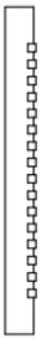
	TITLE	DRAWING NO.	REV
PUYA	Puya LQFP64L 10x10X1.6-0.5PITCH	QRPD-0051	1.0

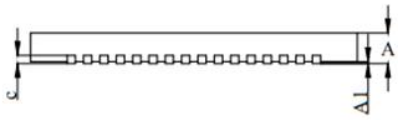
6.2. QFN64

TOP VIEW

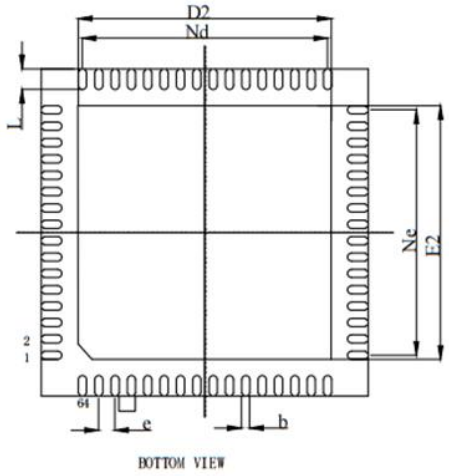


SIDE VIEW





BOTTOM VIEW



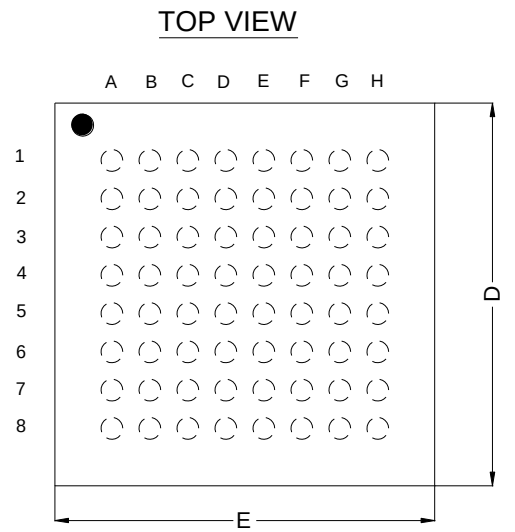
Common Dimensions
(Unit of Measure=millimeters)

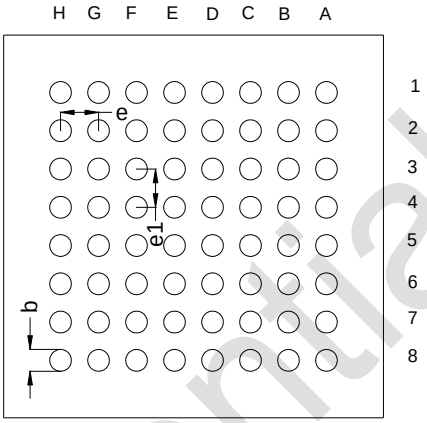
Symbol	Min	Typ	Max
A	0.700	0.750	0.800
A1	0.000	0.020	0.050
b	0.150	0.200	0.250
c		0.203REF	
D	7.900	8.000	8.100
D2	6.400	6.500	6.600
E	7.900	8.000	8.100
E2	6.400	6.500	6.600
e		0.400BSC	
Nd		6.000BSC	
Ne		6.000BSC	
L	0.350	0.400	0.450
h	0.300	0.350	0.400

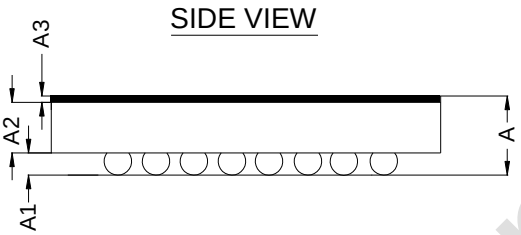
Note：1. Dimensions are not to scale

	TITLE	DRAWING NO.	REV
PUYA	Puya QFN64L 8X8X0.75-0.4PITCH POD	QRPD-0057	1.0

6.3. CSP64







COMMON DIMENSIONS
(Unit of Measure =mm)

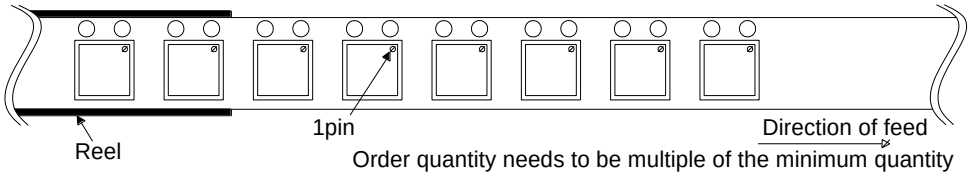
SYMBOL	MIN	TYP	MAX	NOTE
A	-	0.425	-	
A1	0.135	0.1500	0.1650	
A2	0.0.225	0.2500	0.2750	
A3	-	0.0250	-	
D	3.4500	3.5000	3.5500	
E	3.4500	3.5000	3.5500	
b	-	0.2000	-	
e	-	0.4000	-	
e1	-	0.4000	-	

NOTE: 1.Dimensions are NOT to scale.
2.Solder ball composition is SnAg.
3.Product offered with Back Side Coating(BSC)

	TITLE	DRAWING NO.	REV
PUYA	64-ball,8x8 Array,0.4mm pitch Wafer Level Chip ScalePackage with BSC	QRPD-00XX	0.1

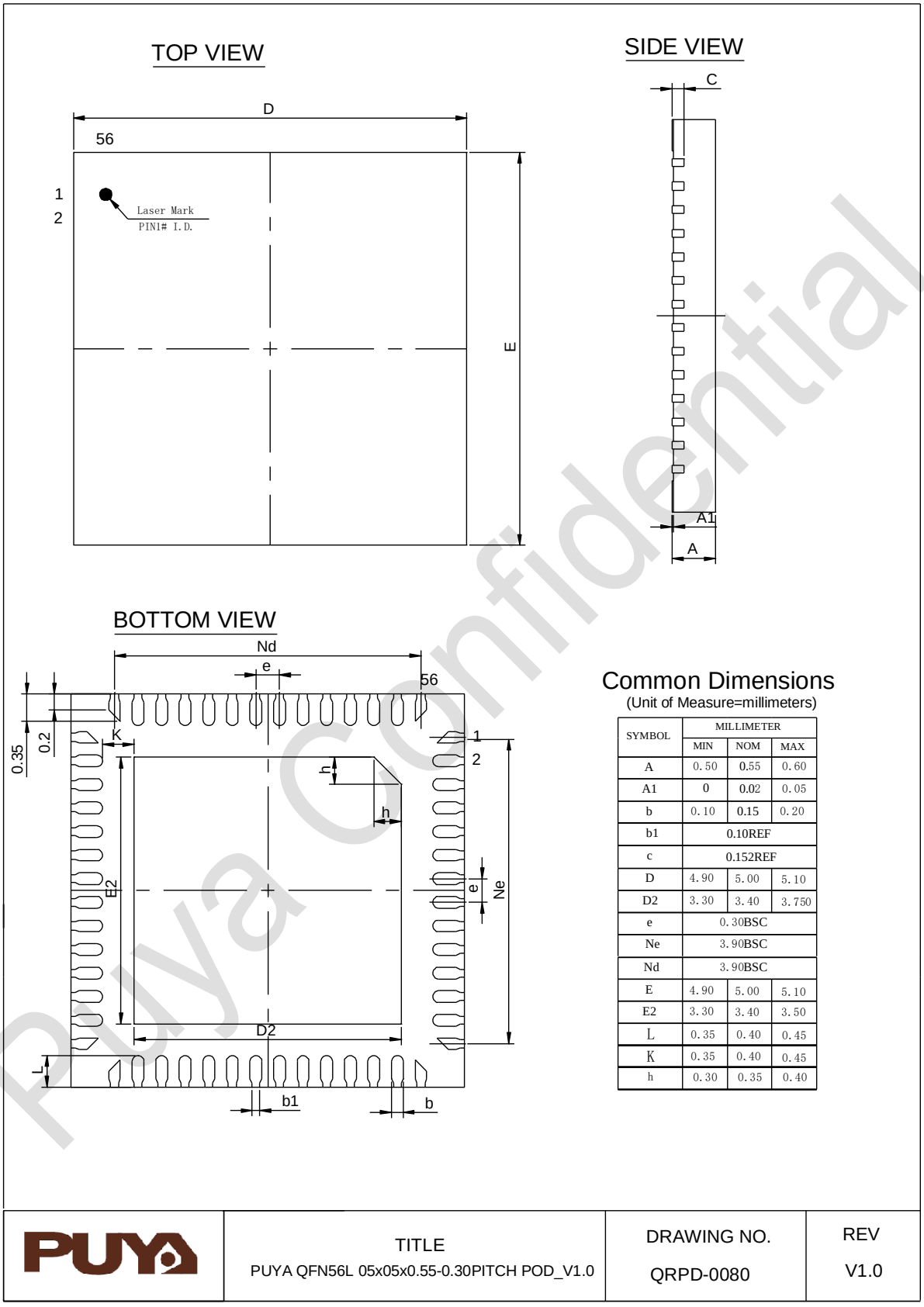
<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	4000pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



Order quantity needs to be multiple of the minimum quantity

6.4. QFN56



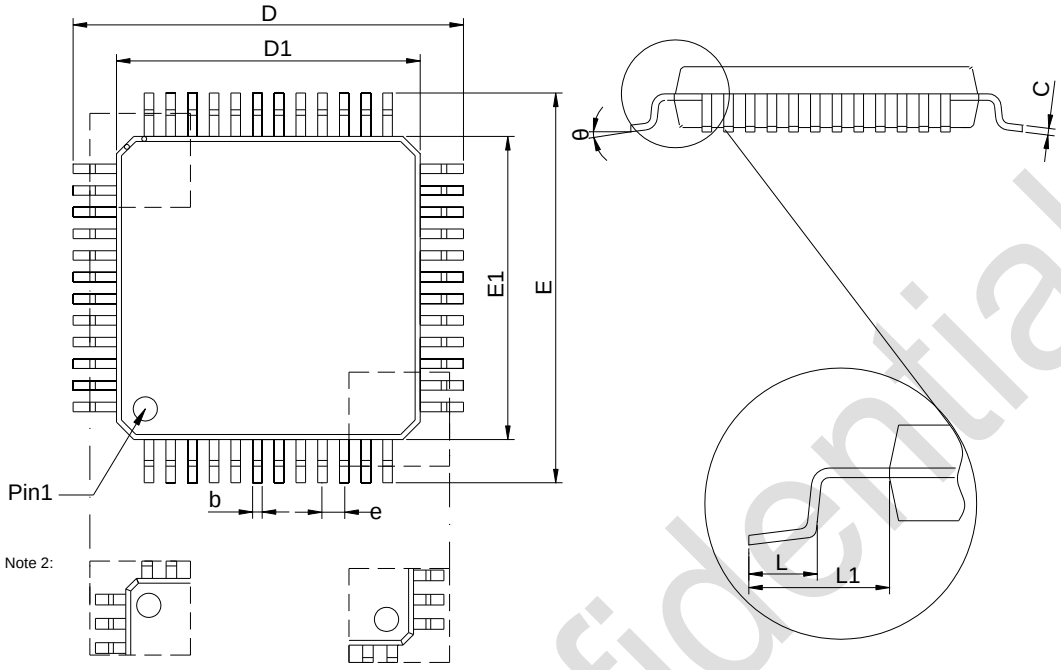
Common Dimensions

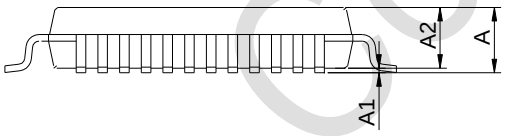
(Unit of Measure=millimeters)

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.50	0.55	0.60
A1	0	0.02	0.05
b	0.10	0.15	0.20
b1	0.10REF		
c	0.152REF		
D	4.90	5.00	5.10
D2	3.30	3.40	3.750
e	0.30BSC		
Ne	3.90BSC		
Nd	3.90BSC		
E	4.90	5.00	5.10
E2	3.30	3.40	3.50
L	0.35	0.40	0.45
K	0.35	0.40	0.45
h	0.30	0.35	0.40

	TITLE	DRAWING NO.	REV
PUYA	PUYA QFN56L 05x05x0.55-0.30PITCH POD_V1.0	QRPD-0080	V1.0

6.5. LQFP48





Common Dimensions

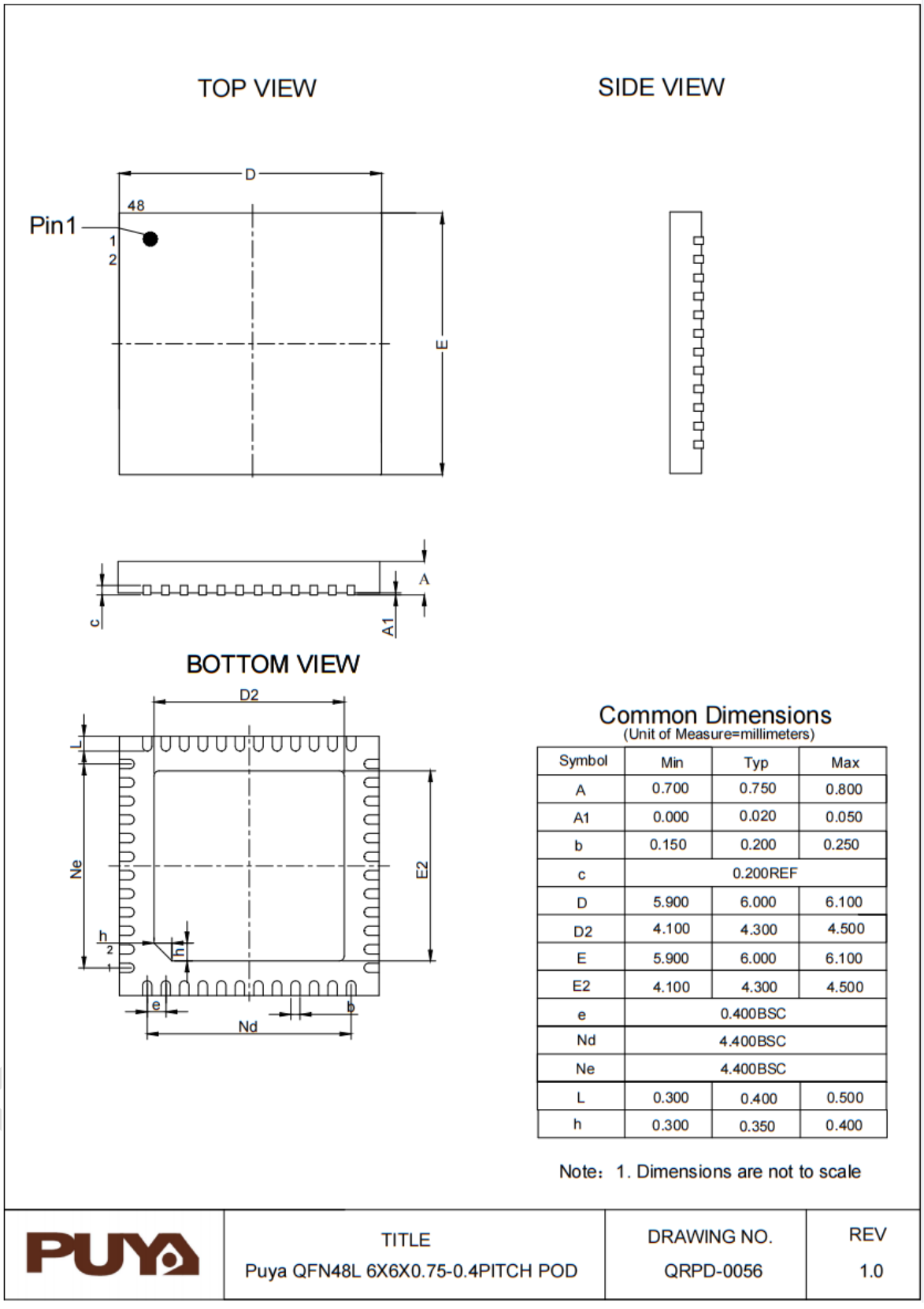
(Unit of Measure=millimeters)

Symbol	Min	Typ	Max
A	-	-	1.600
A1	0.050	-	0.150
A2	1.350	1.400	1.450
b	0.180	-	0.270
c	0.130	-	0.180
D	8.800	9.000	9.200
D1	6.900	7.000	7.100
E	8.800	9.000	9.200
E1	6.900	7.000	7.100
e		0.500BSC	
L	0.450	-	0.750
L1		1.000REF	
θ	0	-	7°

Note：1. Dimensions are not to scale
2.Have two shape can be compatible with each other

	TITLE	DRAWING NO.	REV
PUYA	Puya LQFP48L 7x7X1.6-0.5PITCH	QRPD-0050	1.0

6.6. QFN48



Common Dimensions
(Unit of Measure=millimeters)

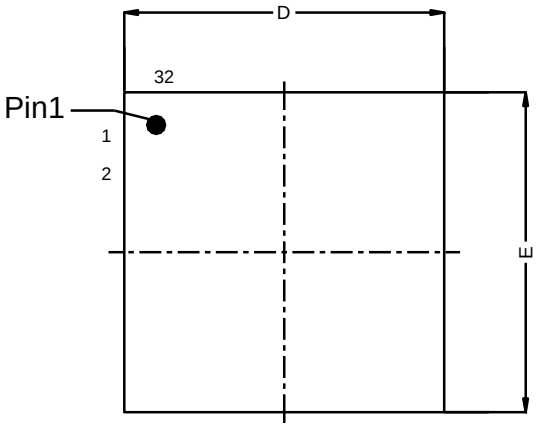
Symbol	Min	Typ	Max
A	0.700	0.750	0.800
A1	0.000	0.020	0.050
b	0.150	0.200	0.250
c		0.200REF	
D	5.900	6.000	6.100
D2	4.100	4.300	4.500
E	5.900	6.000	6.100
E2	4.100	4.300	4.500
e		0.400BSC	
Nd		4.400BSC	
Ne		4.400BSC	
L	0.300	0.400	0.500
h	0.300	0.350	0.400

Note：1. Dimensions are not to scale

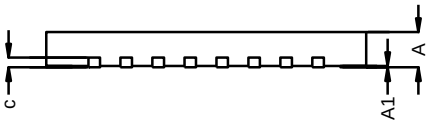
	TITLE	DRAWING NO.	REV
PUYA	Puya QFN48L 6X6X0.75-0.4PITCH POD	QRPD-0056	1.0

6.7. QFN32

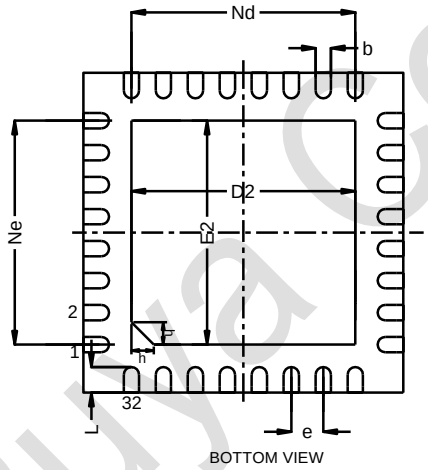
TOP VIEW



SIDE VIEW



BOTTOM VIEW



BOTTOM VIEW

Common Dimensions

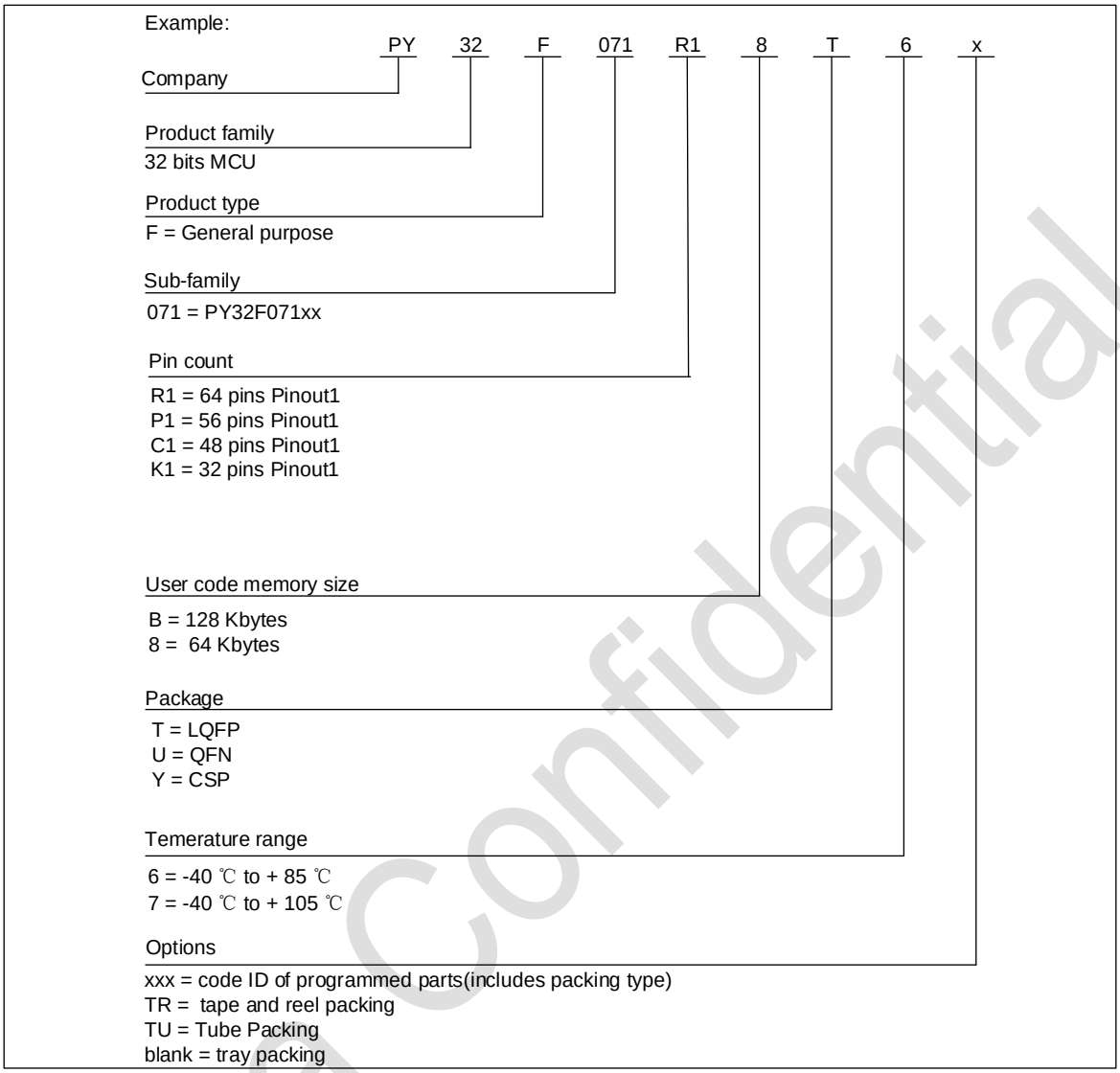
(Unit of Measure=millimeters)

Symbol	Min	Typ	Max
A	0.700	0.750	0.800
A1	0	0.020	0.050
b	0.180	0.250	0.300
c	0.200REF		
D	4.900	5.000	5.100
D2	3.400	3.500	3.600
E	4.900	5.000	5.100
E1	3.400	3.500	3.600
e	0.500BSC		
Nd	3.500BSC		
L	0.350	0.400	0.450
h	0.300	0.350	0.400

Note：1. Dimensions are not to scale

	TITLE	DRAWING NO.	REV
PUYA	Puya QFN32L 5x5X0.75-0.5PITCH POD	QRPD-0042	1.0

7. Ordering Information



8. Version History

Version	Date	Updated record
V0.5	2024.04.19	1. Initial version
V0.6	2024.04.24	1. Update QFN56 package information
V0.7	2024.04.29	1. Add PY32F071x7 version product(T_A=105 ℃)

Puya Semiconductor Co., Ltd.